Maxtang

Shenzhen Maxtang Computer Co., Ltd.

Add：6/F, Block 3, Honghui Industrial Park, Liuxian 2nd Road, Baoan District, Shenzhen, China
Tel :+86 755 86143003
E-mail: info@datangpc.om
www.maxtangpc.com

PRODUCT CATALOG

MAXIMIZING YOUR COMPUTING PRODUCTIVITY

Maxtang
大唐计算机

TH

EM

CONT

ENTS


Maxtang

ABOUT US

Founded in 2009, Maxtang is a leading provider of industrial computers, motherboards, and embedded solutions. Based in Shenzhen, China, we combine research and development, manufacturing, and sales to deliver innovative designs and exceptional customer satisfaction. Our mission is to offer market-leading PCs and motherboards to enterprises and individual users worldwide.

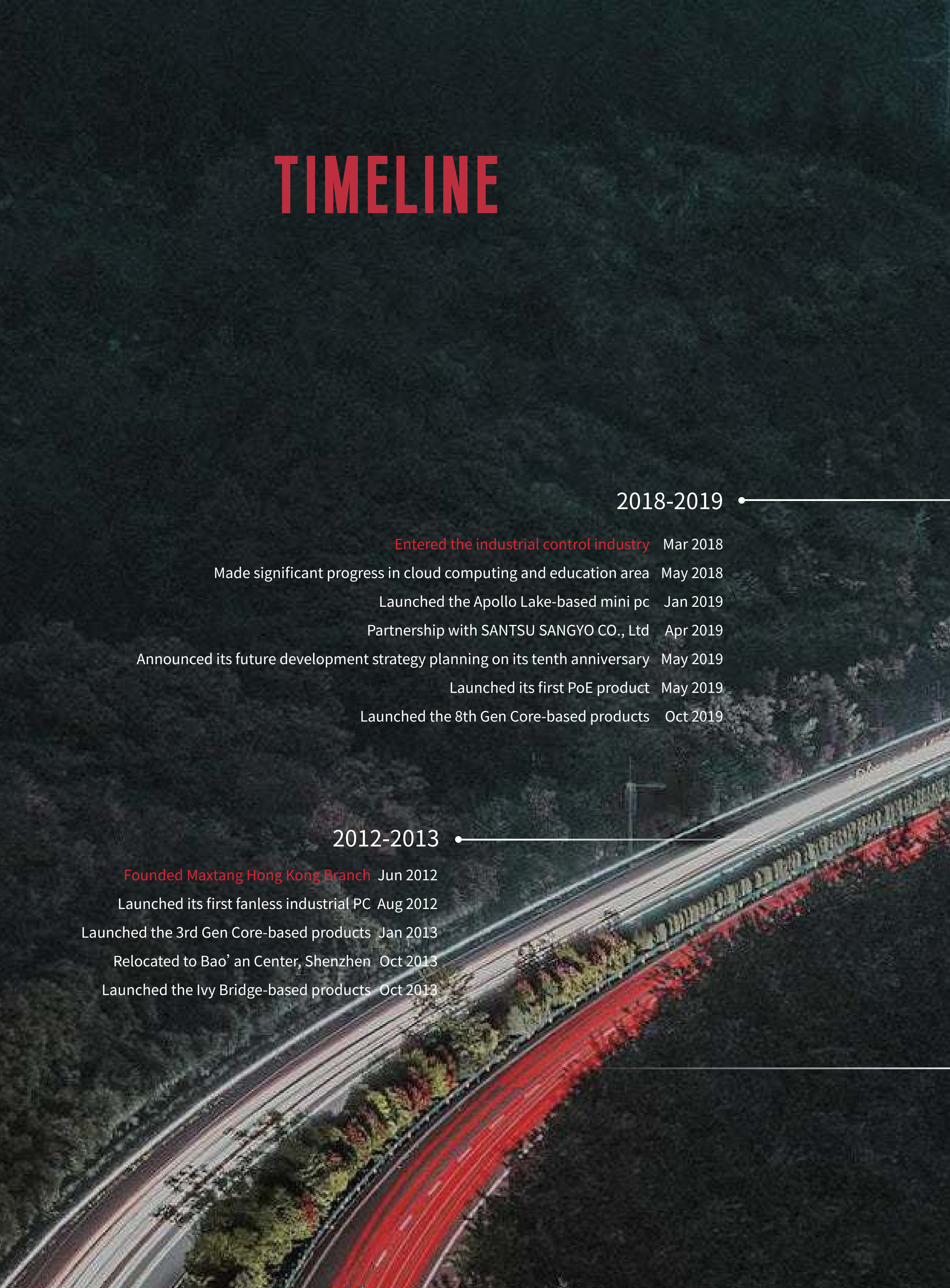
The name Maxtang draws inspiration from the 'Great Tang Dynasty,' a period known for its cultural and artistic achievements. Just as the Tang Dynasty's influence spread across Asia and beyond, we aim to share our business culture and serve global citizens. By maximizing your productivity, we provide high-quality products with cost advantages.

As an associate member of Intel IoT Solutions Alliance and a member of Industrial Solution Builder's Specialist, we are recognized for our expertise in the field. We have also achieved the prestigious "China National High & New Technology Enterprise" qualification and maintain compliance with environmental regulations such as WEEE and RoHS. Additionally, our ISO9001:2015 certification ensures our commitment to quality.

Maxtang offers customized solutions for various industrial applications, including surveillance, digital signage, point of sale, edge computing, and industrial automation. With over 10 years of professional experience, we take pride in delivering high-performance and reliable products.

Joining over 1,500 customers worldwide, choose Maxtang for our customization options, cost advantages, and dedication to excellence in quality and customer support.

- Intel® IoT Solutions Alliance
- Over 1500+ Customers Worldwide
- Over 10 Years of Professional Experience
- Offers Customization with Cost Advantages
- Provides High-Performance & Reliable Products



TIMELINE

2018-2019

Entered the industrial control industry	Mar 2018
Made significant progress in cloud computing and education area	May 2018
Launched the Apollo Lake-based mini pc	Jan 2019
Partnership with SANTSU SANGYO CO., Ltd	Apr 2019
Announced its future development strategy planning on its tenth anniversary	May 2019
Launched its first PoE product	May 2019
Launched the 8th Gen Core-based products	Oct 2019

2012-2013

Founded Maxtang Hong Kong Branch	Jun 2012
Launched its first fanless industrial PC	Aug 2012
Launched the 3rd Gen Core-based products	Jan 2013
Relocated to Bao' an Center, Shenzhen	Oct 2013
Launched the Ivy Bridge-based products	Oct 2013

2020-2022

Partnership with “OITECH” for expanding business in the industrial computer field Apr 2020
Launched the 11th Gen Tiger Lake-based products Apr 2021
Launched the Jasper Lake-based products Sep 2021
Launched the Gemini Lake-based ultra-compact mini pc Dec 2021
Launched the Elkhart Lake-based products Feb 2022
Launched the Alder Lake-based product Jun 2022

2016-2017

Nov 2016 Won the “China National High-Tech Enterprise” Award.
Dec 2016 Launched the Skylake-based products.
Mar 2017 Launched the Kabylake-based products.
Sept 2017 Launched the first AI industrial camera with Intel.
Nov 2017 Passed the certification of ISO9001.

2014-2015

May 2014 Launched the Bay Trail-based products
Aug 2014 Launched the H81 platform-based products.
Sept 2014 Launched the Haswell-based products.
Feb 2015 Launched the Broadwell/Braswell based products.
Mar 2015 Won the “2014 Digital Signage Player Brand Award”.
Oct 2015 Won the “Intel Innovative Technology ” Award.

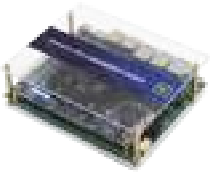
2009-2011

May 2009 Founded in Shenzhen, China.
May 2009 Launched Low-TDP Atom based motherboards

PRODUCT TYPE

Machine Vision

OPS Industrial PC



Phoenix Hill

MiNi PC

Embedded Industrial PC

Embedded Motherboard

PoE Ethernet Card

RTOS

APPLICATIONS

Provide Customized Solutions & Products based on Industrial Needs with Professional Services

- IOT
- Communication
- Industrial Automation
- Energy Management
- Network Security
- Smart Transportation
- Surveillance
- Digital Signage
- Self-Service Terminal
- Data Storage
- Edge Computing
- In-Vehicle Computing

INDUSTRY INFLUENCE

Maxtang has expanded the global market through various trade shows. Pictures are the showcase of the Embedded World Germany, India Expo Convergence, and COMPUTEX Taiwan.

embeddedworld Exhibition&Conference Nürnberg, Germany,2019

COMPUTEX TAIPEI Taipei, Taiwan 2017

EmbeddedTech INDIA EXPO New Delhi, India, 2022, 2023

Product Launch Conference in Shenzhen, China

02

HONORS AND AWARDS

ENTERPRISE HONOR












INTELLECTUAL PROPERTY











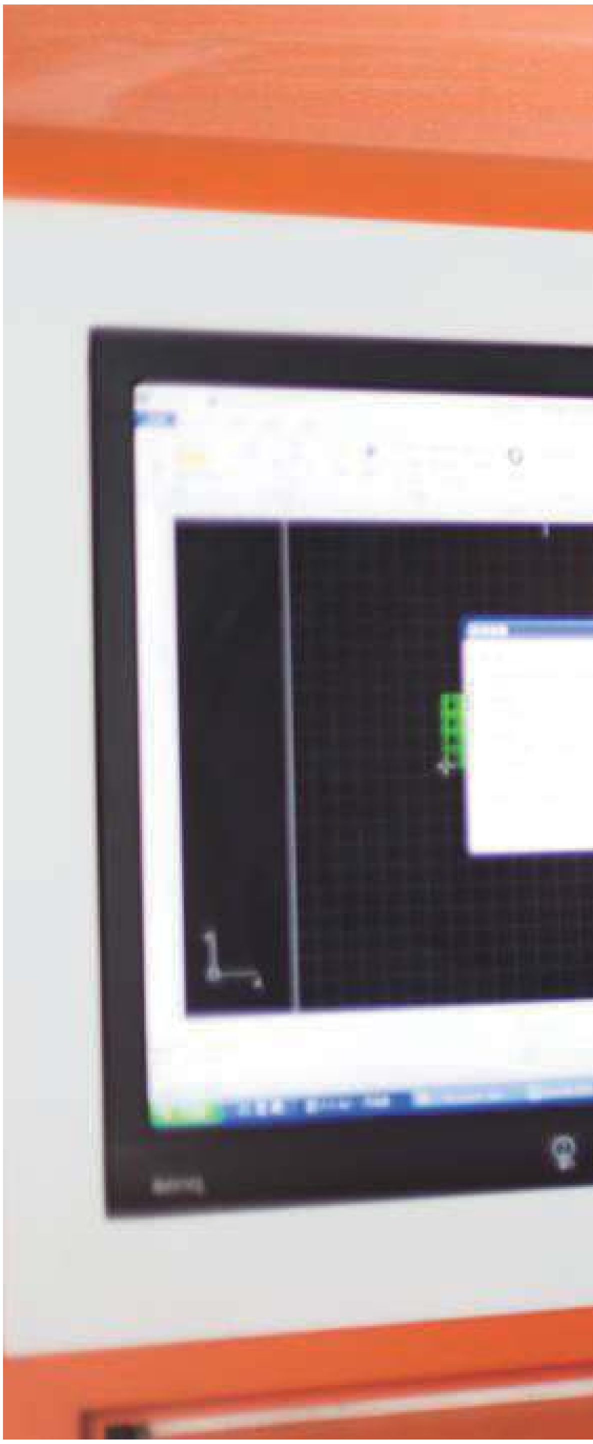


QUALITY
CONTROL

认证证书

三一智造（深圳）有限公司

IATF 16949:2016



- Sanyi Zhizao “三一智造” is an independent subsidiary of Maxtang
- Focusing on manufacturing capabilities, provides powerful supports to Maxtang's supply chain and manufacturing support.


LOCK
POWER LAMP
EMERGENCY STOP

03

RESEARCH AND DEVELOPMENT

RESEARCH AND DEVELOPMENT

The Maxtang R&D team possesses extensive experience in designing and developing specialized software, hardware, and system integration. They exhibit a prompt and accurate response to product development trends and user demands, swiftly translating them into technologically advanced products.

Maxtang has established a comprehensive software development, hardware development, and mechanism design team, ensuring high-quality designs throughout the entire project lifecycle, starting from the initial design phase and continuing until completion.

Furthermore, Maxtang offers a wide range of engineering and production services for embedded boards and systems. These services encompass turnkey system design and construction, along with embedded design support services such as system and board 3D model assistance, reinforcement services, board modifications, and more.

Maxtang excels in managing the product lifecycle and recognizes its significance within various critical industrial applications.

Technical Support

1/Product development and engineering design

- MIL-STD and industrial system design
- Thermal design
- Simulation
- 3D CAD design and modeling support
- Software and BIOS support

2/Mass Production Services

- Board modification
- Sub-system integration
- Ruggedization
- Extended temperature selection

3/Product Life Cycle Management

- Customized BOM support
- Hardware, BIOS, and firmware control
- EOL management
- Extended inventory availability

SOFTWARE SUPPORT

Excellence in Engineering Technology

- Our team of experienced engineers assists customers in analyzing PCB designs and prototypes, ensuring optimal results.
- We employ efficient testing plans to thoroughly analyze all causal factors, enabling us to deliver exceptional products.
- Our senior engineers are experts in process quality planning and implementation, ensuring top-notch results.

Professional and Highly Skilled Team

- Our team consists of highly qualified and experienced professionals, dedicated to delivering excellence.
- Over 50% of our employees hold advanced degrees, reflecting our commitment to expertise.
- Our team possesses exceptional execution capabilities and continually strives for self-improvement.

Stringent Quality Control

- We utilize advanced SPI+AOI optical inspection equipment to achieve 100% quality assurance.
- Our process quality is monitored at every stage, guaranteeing superior performance.
- With dual quality management system certifications, we are committed to continuous improvement and customer satisfaction.
- We have obtained multiple high-standard international quality certifications, reinforcing our commitment to excellence.

High-Quality Manufacturing Process and Materials

- We use only the best materials for our manufacturing processes.
- Our selection includes ALPHA brand lead-free solder paste, ensuring optimal results.
- We source high-purity lead-free solder wire from trusted suppliers like Yuntie.
- We strictly avoid the use of secondary processed materials, ensuring superior product quality.

Comprehensive Service System

- We are committed to delivering services on time, with the highest quality and quantity.
- Our customer-centric approach places our clients' needs at the forefront.
- We provide strong value-added after-sales services, ensuring customer satisfaction.
- With our integrated one-stop solution services, we offer a seamless and comprehensive experience.

Precise Material Quality Control

- Our rigorous quality control measures include thorough inspections of incoming materials.
- Before shipment, we confirm the quality of outgoing materials, ensuring our customers receive the best products.
- Our commitment to quality is exemplified by pre-production quality re-inspections and in-process quality testing.
- We conduct post-production quality analysis and confirmation to guarantee excellence.

MANUFACTURING CAPABILITIES

12 zones Dual Rail SMT Reflow Oven KTR-1200D/2 sets

High-speed automatic optical inspection equipment AOI JTA-680D/2 sets

Intelligent multi-functional placement machine Panasonic NPMTT 2/2 sets

Intelligent high-speed placement machine-Panasonic NPMD3/6 sets

Automated offline AOI-JTA-680D/2 sets

High-speed automatic optical inspection equipment SPI Jintuo JTREFINE-C/2 sets

High-speed printer Densen Hito / 2 sets

Optical automatic electronic inspection equipment-Blueeye FI600/2 sets

Automated BGA automatic welding equipment Zhuo Mao ZMR6200/2 sets

Double wave soldering equipment Mindray Mairay/2 sets

Automatic simulation transportation vibration table DK5024/1 set

Automatic unloading machine ULF-390A2/1 set

04

LIST OF PRODUCTS

INDUSTRIAL MOTHERBOARD

TL-10

Mini-ITX

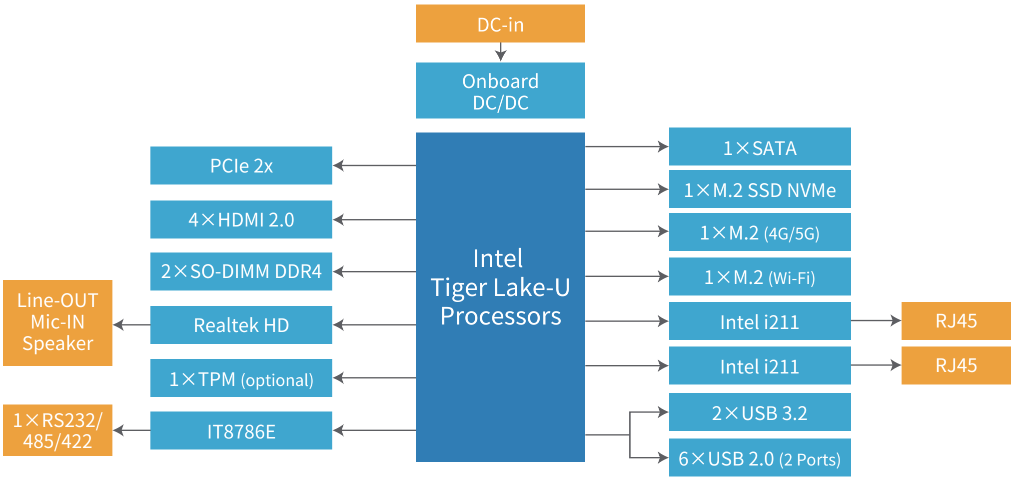
FEATURES

- CPU: Intel Tiger Lake-U Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64GB
- I/O Interface: 2xLAN, 1xCOM(header), 2xUSB3.2, 6xUSB2.0(4*header), LPC, Audio
- Display via: 4xHDMI2.0
- Ethernet: 10/100/1000Mbps

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 6305	i3 1115G4	i5 1145G7	i7 1165G7
Memory	2×SO-DIMM DDR4, Max 64GB			
Storage	1×SATA 3.0, 1×M.2 for 2280 SSD NVMe			
I/O Interface	2×LAN, 1×COM, 2×USB 3.2, 6×USB 2.0, 1×Mic in, 1×Line out, 4×HDMI			
GPU	Depends on CPU			
Size	170mm×170mm			
Power	12V DC_in			
Temperature	-20°C~60°C			

WL-10

Mini-ITX

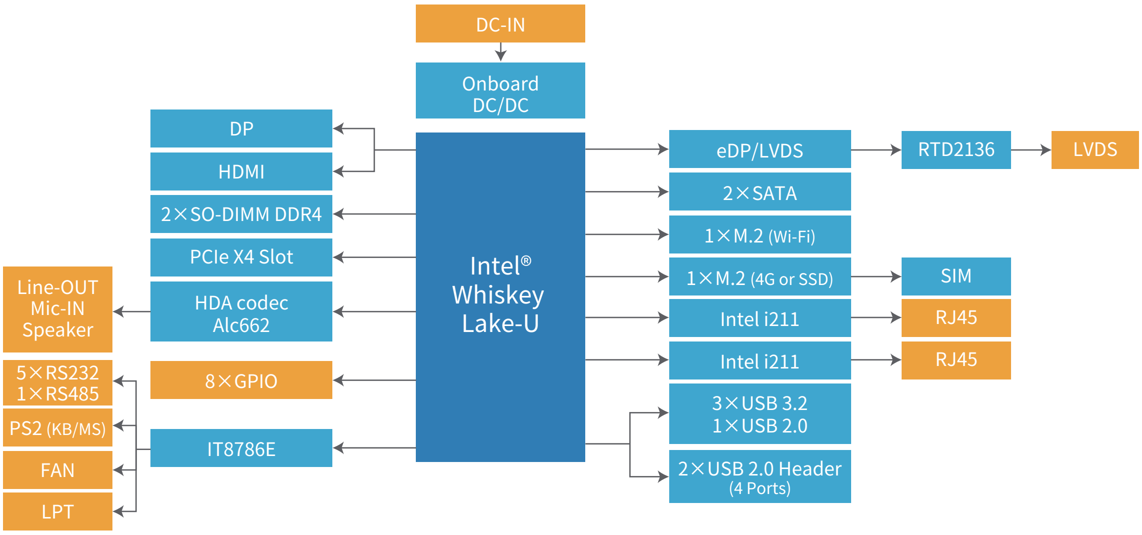
FEATURES

- CPU: Intel Whiskey Lake/Comet Lake-U Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64GB
- I/O Interface: 2xLAN, 6xCOM(header), 3xUSB3.2 5xUSB2.0(4*header), LPT, PS/2, GPIO, Audio
- Display via: 1xHDMI, 1xDP, 1x LVDS/eDP
- Ethernet: 10/100/1000Mbps)

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 4205U	i3 8145U	i5 8265U	i7 8565U/8665U
Memory	Dual Channel 2×DDR4-2400MHz, Max 64GB			
Storage	2×SATA 3.0, 1×M.2 for 4G/2280 SSD			
I/O Interface	2×LAN, 6×COM, 3×USB 3.2, 5×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×DP, 8×GPIO 1×LPT, 1×PS/2, 1×LVDS/eDP			
GPU	Intel UHD Graphics 610/620			
Size	170mm×170mm			
Power	12V DC_in			
Temperature	-20°C~60°C			

WL-35

3.5” Disk Size SBC

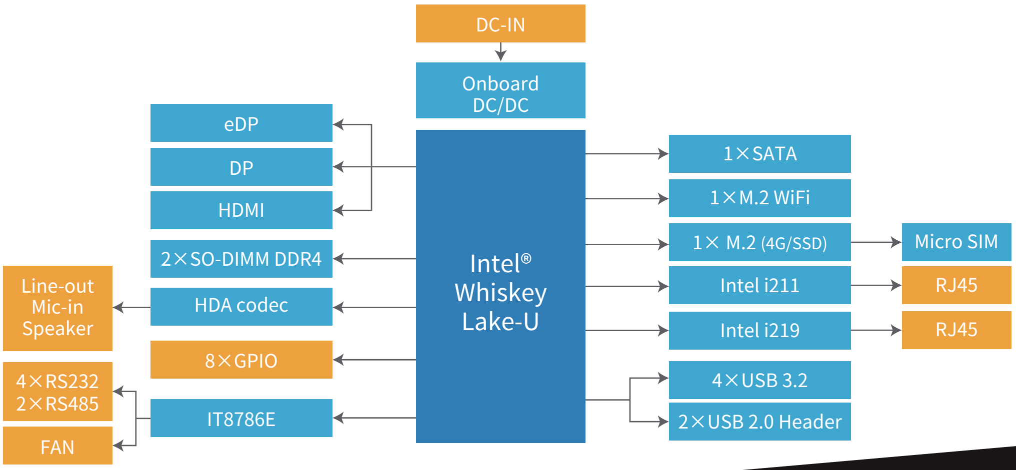
FEATURES

- CPU: Intel Whiskey Lake-U Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64GB
- I/O Interface: 2xLAN, 6xCOM(header), 4x USB3.2 2xUSB2.0(header), GPIO, LPC , Audio
- Display via: 1xHDMI, 1xDP,1x eDP
- Ethernet: 10/100/1000 Mbps

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 4205U	i3 8145U	i5 8265U
Memory	Dual Channel SO-DIMM DDR4, Max 64GB		
Storage	1×M.2 for 4G/2242 SSD, 1×SATA 3.0		
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 2×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×DP, 8×GPIO 1×eDP		
GPU	Intel UHD Graphics		
Size	146mm×102mm		
Power	12V/19V DC input		
Temperature	-20°C~60°C		

APL-35

3.5” Disk Size SBC

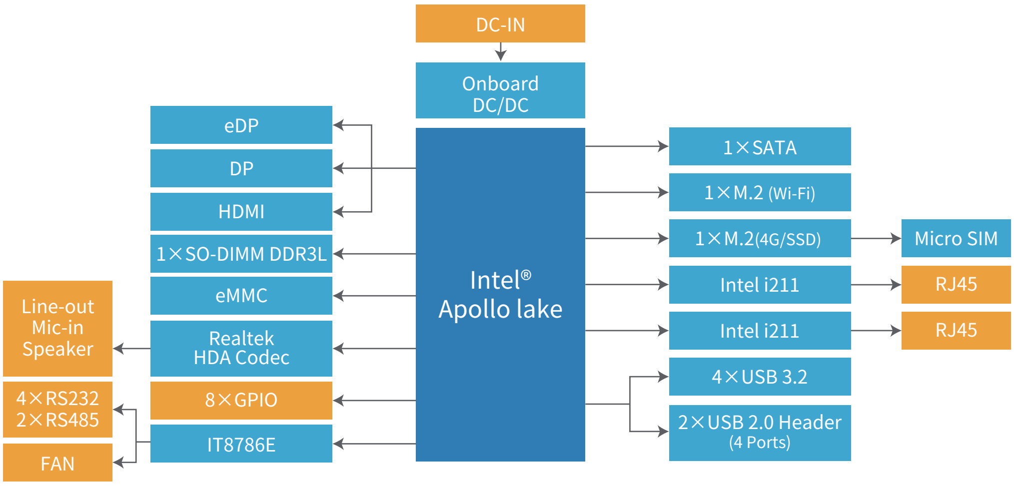
FEATURES

- CPU: Intel Apollo Lake BGA Processor
- Memory: Single Channel SO-DIMM DDR3L up to 8GB
- I/O Interface: 2xLAN, 6xCOM(header), 4xUSB3.2 4xUSB2.0(header), GPIO, LPC Optional, Audio,
- Display via: 1xHDMI, 1xDP, 1x eDP
- Storage: SATA3.0, M.2, eMMC Optional

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES

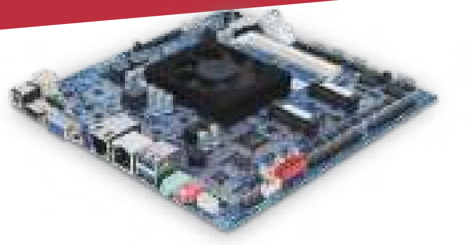


SPECIFICATIONS

CPU	J3355	J3455	J4205	N3350	N3450	N4200
Memory	1×SO-DIMM DDR3L, Max 8GB					
Storage	1×M.2 for 4G or 2242 SSD, 1×SATA 3.0					
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×DP, 8×GPIO 1×eDP					
GPU	Intel HD Graphics 500					
Size	146mm×102mm					
Power	12/19V DC input					
Temperature	-20°C~60°C					

BW-10

Mini-ITX



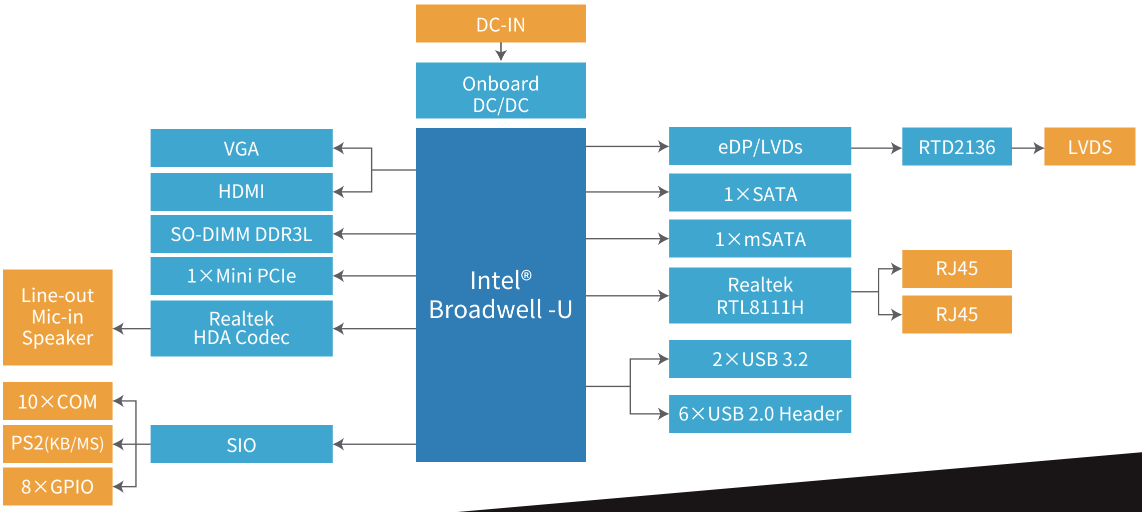
FEATURES

- CPU: Intel Broadwell-U Celeron, Core Processor
- Memory: Single Channel SO-DIMM DDR3L up to 8 GB
- I/O Interface: 2xLAN, 10xCOM(header),2xUSB3.2, 6xUSB2.0(Header), PS/2(header), GPIO, Audio
- Display via: 1xHDMI, 1xVGA,1xLVDS/eDP
- Storage: SATA3.0, mSATA

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 3205U	i3 5010U	i5 5200U	i7 5500U
Memory	1×DDR3L-1600MHz, Max 8GB			
Storage	1×mSATA, 1×SATA 3.0			
I/O Interface	2×LAN, 10×COM, 3×USB 3.2, 6×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×VGA, 1×GPIO 1×LVDS/eDP			
GPU	Intel HD Graphics			
Size	170mm×170mm			
Power	12V DC-in			
Temperature	-20°C~60°C			

BW-35

3.5” Disk Size SBC

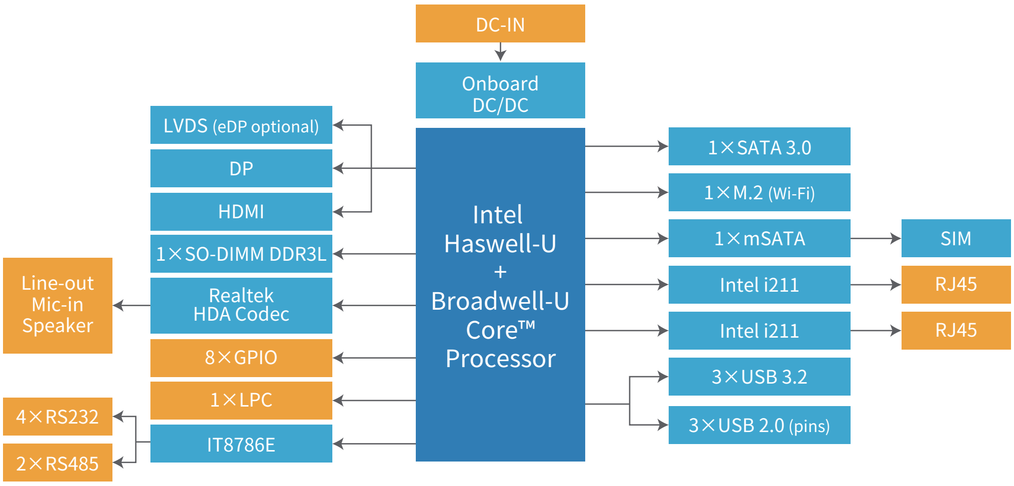
FEATURES

- CPU: Intel Broadwell/Haswell-U Processor
- Memory: Single Channel SO-DIMM DDR3L up to 8GB
- I/O Interface: 2xLAN, 6xCOM(header), 3x USB3.2, 3xUSB2.0(2*header), GPIO, LPC, Audio
- Display via: 1xHDMI, 1xDP, 1xLVDS/eDP
- Storage: SATA3.0, mSATA

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	i5 4200U	i7 4500U	i3 5005U	i5 5200U	i7 5500U
Memory	1×DDR3L-1600MHz, Max 8GB				
Storage	1×mSATA, 1×SATA 3.0				
I/O Interface	2×LAN, 6×COM, 3×USB 3.2, 3×USB 2.0, 1×HDMI, 1×DP, 8×GPIO, 1×LVDS/eDP				
GPU	Intel HD Graphics				
Size	146mm×102mm				
Power	12V DC-in				
Temperature	-20°C~60°C				

BYT-33

238 mm x 146 mm

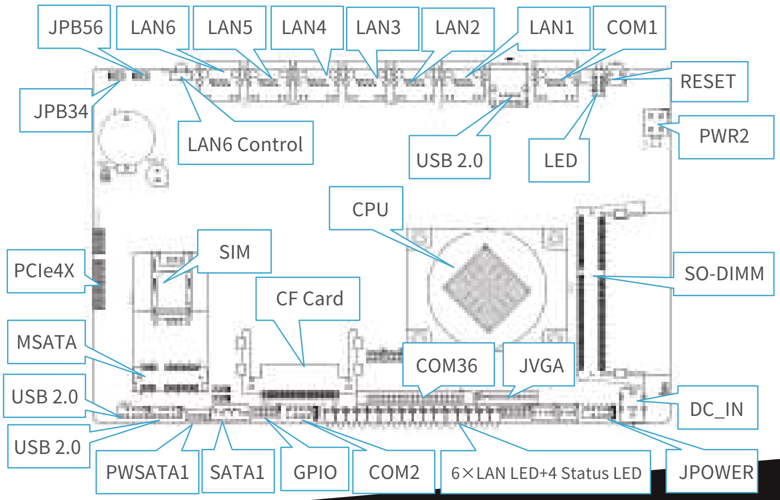
FEATURES

- CPU: Intel Bay Trail Celeron J1900 Processor
- Memory: Single Channel SO-DIMM DDR3L up to 8GB
- I/O Interface: 6xLAN, 6xCOM/2COM (1*port default+5*header) 6xUSB2.0(4*header), GPIO, LPC
- Display via: 1xVGA
- Storage: CF Card, mSATA/SATA2.0

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron J1900
Memory	1× SO-DIMM DDR3L-1333MHz, Max 8GB
Storage	1×CF Card, 1×mSATA/SATA
I/O Interface	6×LAN, 6×COM, 6×USB 2.0, 1×VGA, 8×GPIO
GPU	Intel HD Graphics
Size	238mm×146mm
Power	12V DC-in
Temperature	-20°C~60°C

BYT-35

3.5” Disk Size SBC

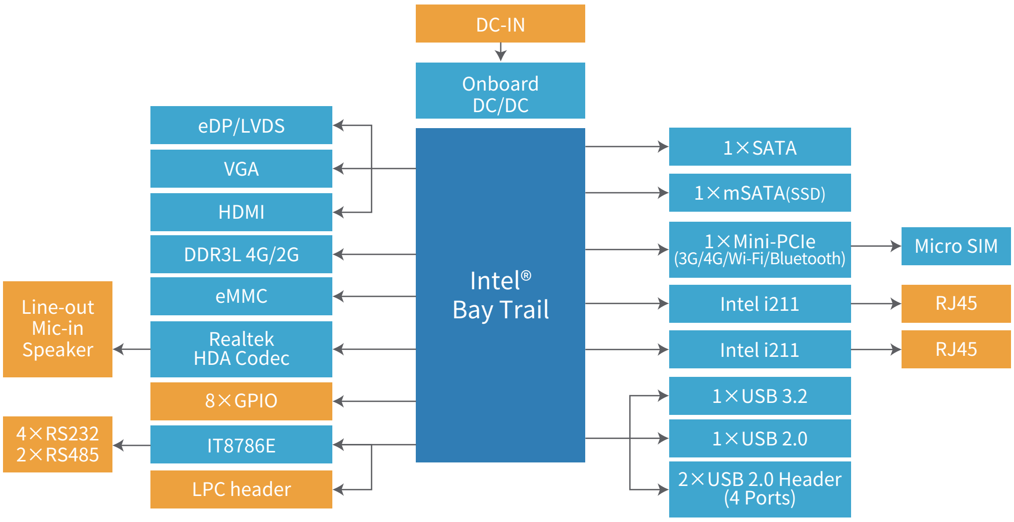
FEATURES

- CPU: Intel Bay Trail BGA Processor
- Memory: Dual Channel SO-DIMM DDR3L up to 4GB
- I/O Interface: 2xLAN, 6xCOM(header), 1x USB3.2, 5xUSB2.0(4*header), GPIO, LPC Optional, Audio
- Display via: 1xHDMI, 1xVGA, 1xLVDS/eDP
- Storage: SATA, mSATA, eMMC optional

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	J1800	J1900	N2940
Memory	Dual Channel SO-DIMM DDR3L, Max 4GB		
Storage	1×mSATA for SSD, 1×SATA 2.0		
I/O Interface	2×LAN, 6×COM, 1×USB 3.2, 5×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×VGA, 8×GPIO 1×LVDS/eDP		
GPU	Intel HD Graphics		
Size	146mm×102mm		
Power	12V DC-in		
Temperature	-20°C~60°C		

BYT-60

Mini-ITX

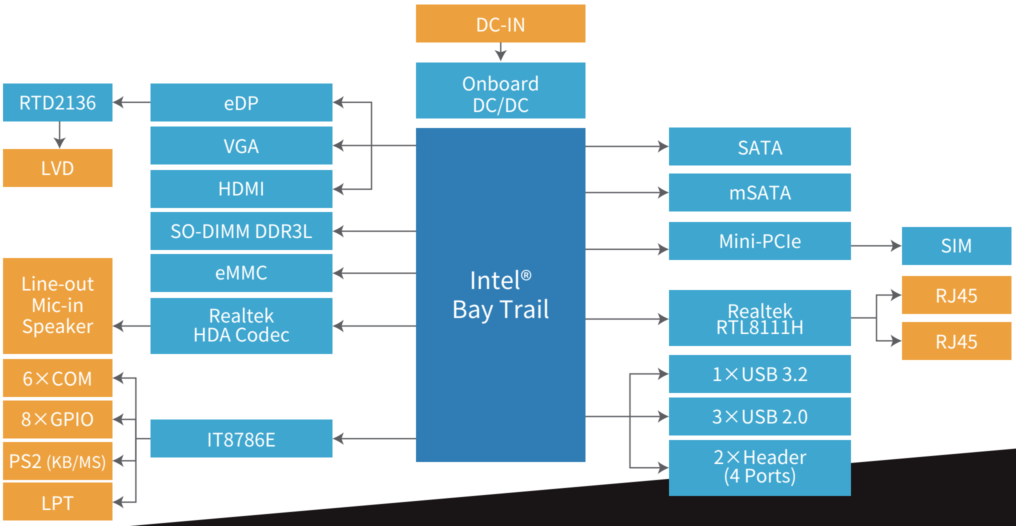
FEATURES

- CPU: Intel Bay Trail Celeron, Atom Processors,
- Memory: Single Channel SO-DIMM DDR3L up to 8GB
- I/O Interface: 2xLAN, 6xCOM(header), 1xUSB3.2,GPIO, 5xUSB2.0 (1*Port + 4*header)PS/2, LPT, Audio
- Display via: 1xVGA,1xHDMI, 1xLVDS (eDP, optional)
- Storage: SATA2.0, mSATA

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	J1800	J1900	N2940
Memory	1×DDR3L-1333MHz, Max 8GB		
Storage	1×mSATA, 2×SATA 2.0		
I/O Interface	2×LAN, 6×COM, 1×USB 3.2, 5×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×VGA, 8×GPIO 1×LVDS/eDP, 1×PS/2, 1×LPT		
GPU	Intel HD Graphics		
Size	170mm×170mm		
Power	12V DC-in		
Temperature	-20°C~60°C		

CFD-10

Mini-ITX

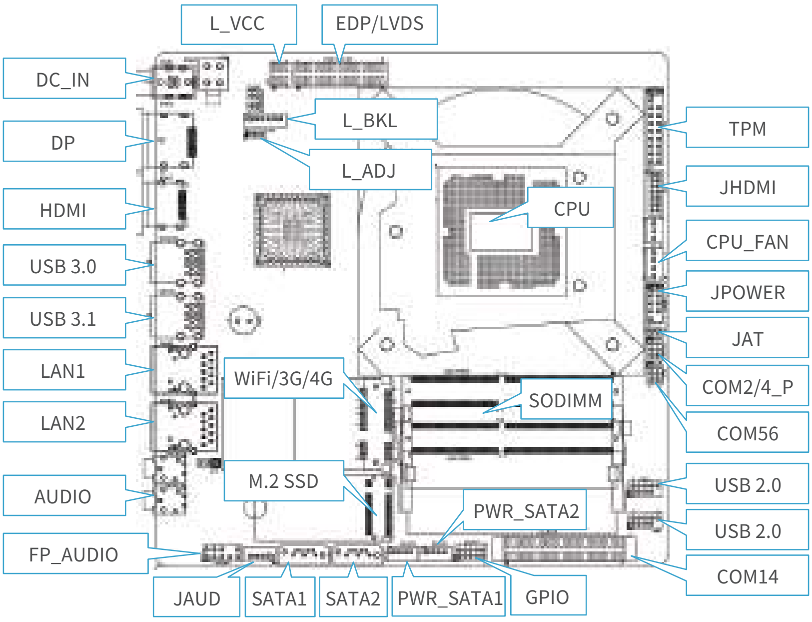
FEATURES

- CPU: Intel Coffee Lake 8th, 9th Gen Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64 GB
- I/O Interface: 2xLAN, 6x COM(2*header), 4x USB2.0(header) 4x USB3.2, GPIO, TPM*header, Audio
- Display via: 2xHDMI(1*header), 1xDP, 1xLVDS/eDP
- Storage: SATA3.0, M.2

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Intel Coffee Lake 8th/9th Gen
Memory	2×SO-DIMM DDR4-2400/2666 MHz, Max 64GB
Storage	1×M.2 for 2242 SSD, 2×SATA 3.0
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI 1.4, 1×HDMI(Pins) 1×DP, 8×GPIO, 1×LVDS(eDP Optional)
GPU	Integrated Graphics
Size	170mm×170mm
Power	19V DC-in
Temperature	-20°C~60°C

CLD-15

Mini-ITX

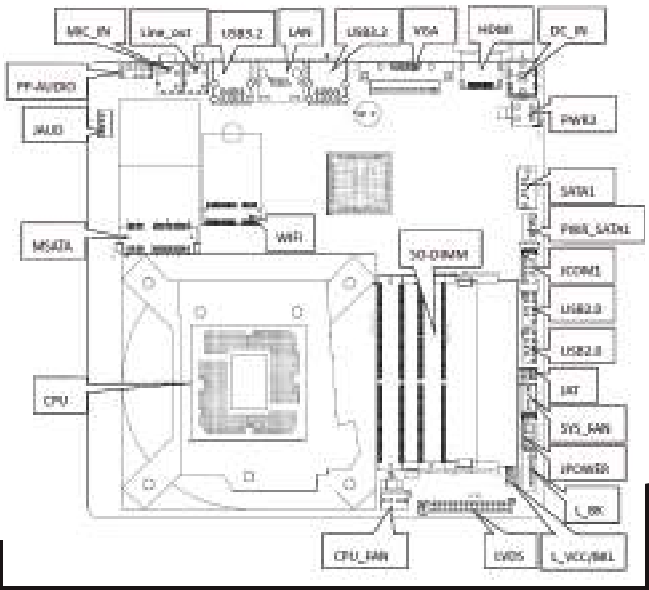
FEATURES

- CPU: Intel 6th, 7th, 8th, 9th Gen Desktop Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64 GB
- I/O Interface: 1xLAN, 1xCOM(header), 4xUSB3.2, 4xUSB2.0(Header), Audio
- Display via: 1xHDMI1.4, 1xVGA, 1xLVDS
- Storage: SATA3.0, mSATA

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Intel 6th/7th/8th/9th
Memory	2×SO-DIMM DDR4-2400/2666MHz, Max 64GB
Storage	1×mSATA, 1×SATA 3.0
I/O Interface	1×LAN, 1×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×VGA, 1×LVDS
GPU	Integrated Graphics
Size	170mm×170mm
Power	19V DC-in
Temperature	-20°C~60°C

FP-10

Mini-ITX

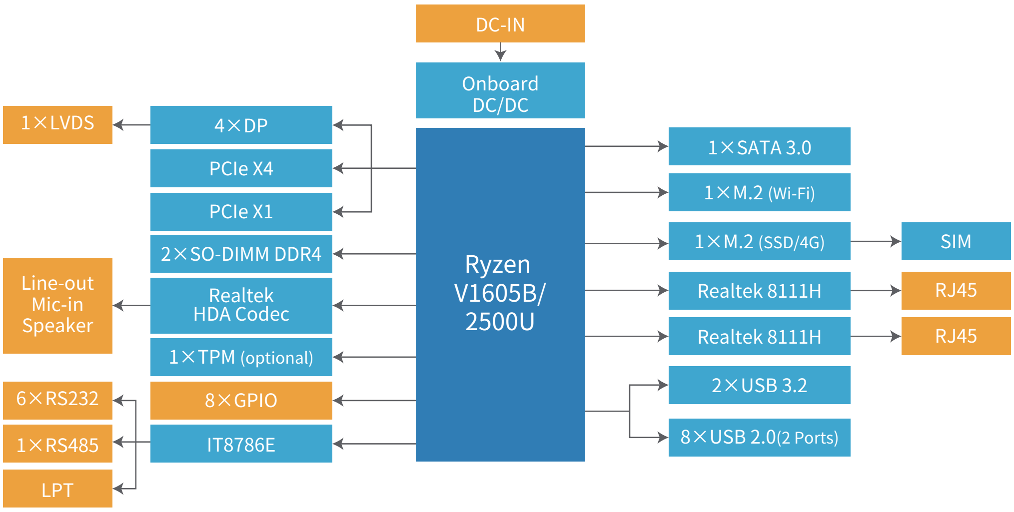
FEATURES

- CPU: Ryzen™ 5 2500U, V1605B Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 32GB
- I/O Interface: 2xLAN, 6xCOM(header), 2xUSB3.2, 8xUSB2.0(6*header), GPIO, LPT,LPC,PS/2, Audio
- Display via: Up to 4xDP1.4 (DP1/eDP/LVDS optional)
- Storage: SATA3.0, M.2

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	V1605B	2500U	
Memory	2×SO-DIMM DDR4, Max 32GB		
Storage	1×M.2 for 4G/2280 SSD, 1×SATA		
I/O Interface	2×LAN, 6×COM, 2×USB 3.2, 8×USB 2.0, 1×Mic in/Line out, 4×DP, 8×GPIO, 1×LVDS/eDP 1×JLPT, 1×PS2_H		
GPU	AMD Radeon Vega 8 Graphics		
Size	170mm×170mm		
Power	12V DC-in		
Temperature	-20°C~60°C		

HWD-70

Micro ATX

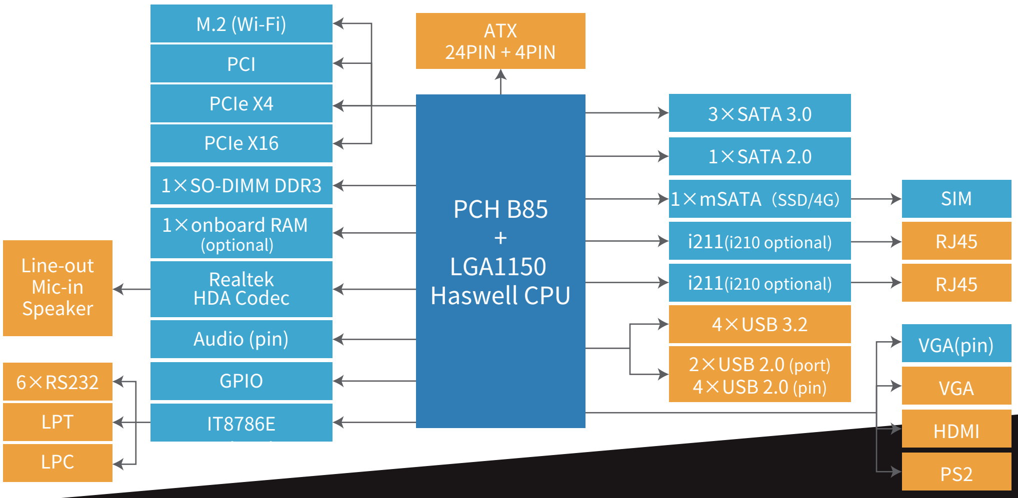
FEATURES

- CPU: Intel Haswell Processor
- Memory: 1xSO-DIMM DDR3, Support Dual Channel up to 16GB
- I/O Interface: 2xLAN, 6xCOM(header), 4xUSB3.2, 6xUSB2.0(4*header), PS/2, GPIO, LPT, LPC, Audio,
- Display via: 1xHDMI1.4, 2xVGA(1*onboard pins)
- Storage: SATA3.0, SATA2.0,mSATA

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	LGA1150 CPU
Memory	1×SO-DIMM DDR3L，Support Dual Channel on-board, Max 8GB
Storage	1×mSATA 3.0, 1×SATA 2.0, 3×SATA 3.0
I/O	2×LAN, 6×COM(header), 4×USB3.2, 6×USB2.0(4*header), PS/2, GPIO, LPT, LPC, Audio
GPU	Intel HD Graphics
Size	244mm×200mm
Power	ATX_24V
Temperature	-40°C~60°C

HWM-10

Mini-ITX

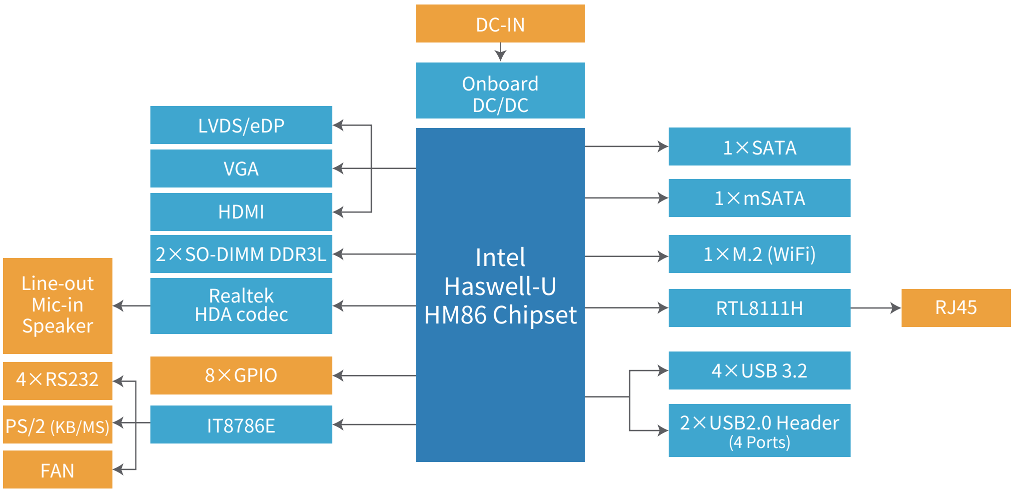
FEATURES

- CPU: Intel Haswell Celeron Pentium, Core Processor
- Memory: Dual Channel SO-DIMM DDR3L up to 32GB
- I/O Interface: 1xLAN, 4xCOM(header), 4x USB3.2 4xUSB2.0(header), GPIO, PS/2, Audio
- Display via: 1xHDMI, 1xVGA, 1x eDP/LVDS
- Storage: SATA3.0, mSATA

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Haswell FCPGA946
Memory	2×DDR3L SO-DIMM, Max 32GB
Storage	1×SATA 3.0, 1×mSATA
I/O Interface	1×LAN, 4×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×VGA, 8×GPIO 1×PS/2, 1×LVDS/eDP
GPU	Intel Integrated Graphics
Size	170mm×170mm
Power	12V DC-in
Temperature	-20°C~60°C

KL-10

Mini-ITX

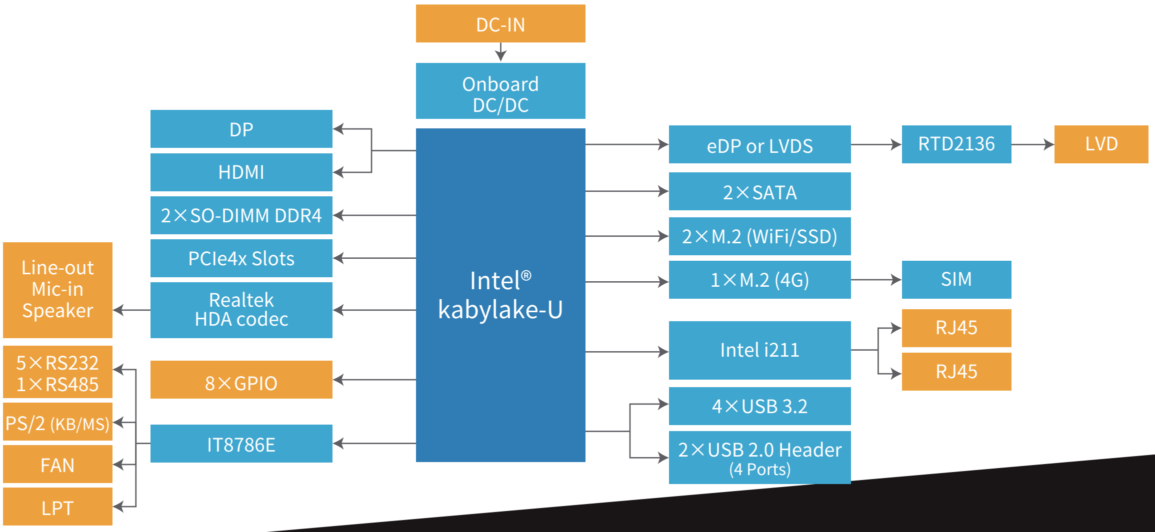
FEATURES

- CPU:Intel Kaby Lake-U Celeron,Core Processor
- Memory:Dual Channel SO-DIMM DDR4 up to 32 GB
- IO Interface:2xLAN,6xCOM(header),4xUSB3.2, 4xUSB2.0(header),GPIO, PS/2(header),LPT,Audio Display via:1xHDMI,1xDP,1x LVDS/eDP
- Ethemet:10/100/1000Mbps
- Storage:SATA3.0, M.2, eMMC Optional
- Expansion:M.2 for WiFi, PCle 4X
- Power: 12V DC input

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



DC-IN

Onboard DC/DC

Intel® kabylake-U

DP

HDMI

2×SO-DIMM DDR4

PCIe4x Slots

Realtek HDA codec

Line-out
Mic-in
Speaker

8×GPIO

IT8786E

5×RS232
1×RS485

PS/2 (KB/MS)

FAN

LPT

eDP or LVDS

RTD2136

LVD

2×SATA

2×M.2 (WiFi/SSD)

1×M.2 (4G)

SIM

Intel i211

RJ45

RJ45

4×USB 3.2

2×USB 2.0 Header (4 Ports)

SPECIFICATIONS

CPU	Celeron 3865U	i3 7100U	i5 7200U	i7 7500U
Memory	Dual channel SO-DIMM DDR4, Max 32GB			
Storage	1×M. 2 for 4G or 2242 SSD, 2×SATA 3.0			
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×DP, 8×GPIO 1×PS/2, 1×LVDS/eDP			
GPU	Intel HD Graphics			
Size	170mm×170mm			
Power	12V DC-in			
Temperature	-20°C~60°C			

KL-20

Mini-ITX

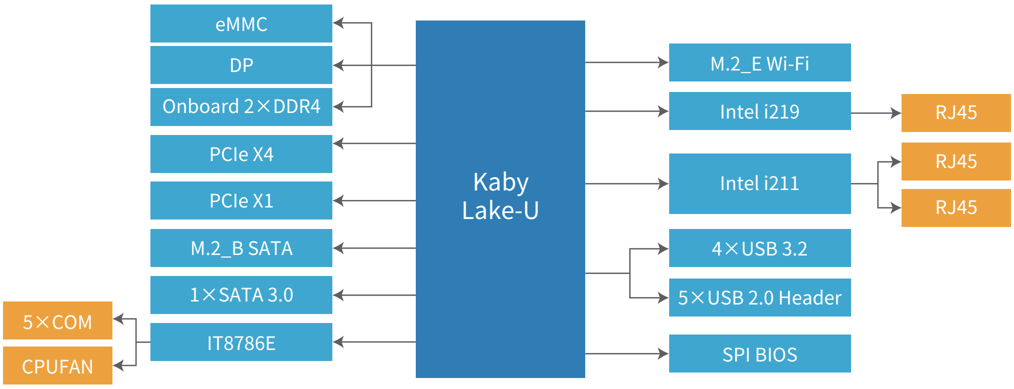
FEATURES

- CPU: Intel Kaby Lake-U Core and Celeron BGA processors
- Memory: Dual channel DDR4 max 32 GB
- Display: DP
- Ethernet: Support 10/100/1000 Mbps ethernet card
- Storage: SATA3.0, M.2, PCIe X4, PCIe X1
- Power: 16V-36V 4-pin power

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES

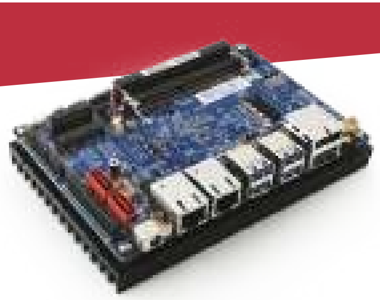


SPECIFICATIONS

CPU	Celeron 3865U	i5 7300U	i5 7200U
Memory	2×DDR4, Max 32GB		
Storage	1×SATA 3.0, 1×M.2 for 2242/2280 SSD		
I/O Interface	3×LAN, 5×COM, 4×USB 3.2, 5×USB 2.0, 1×DP		
GPU	Intel HD Graphics 610/620		
Size	169mm×120mm		
Power	16~36V DC-in		
Temperature	-20°C~60°C		

KL-35

3.5” Disk Size SBC



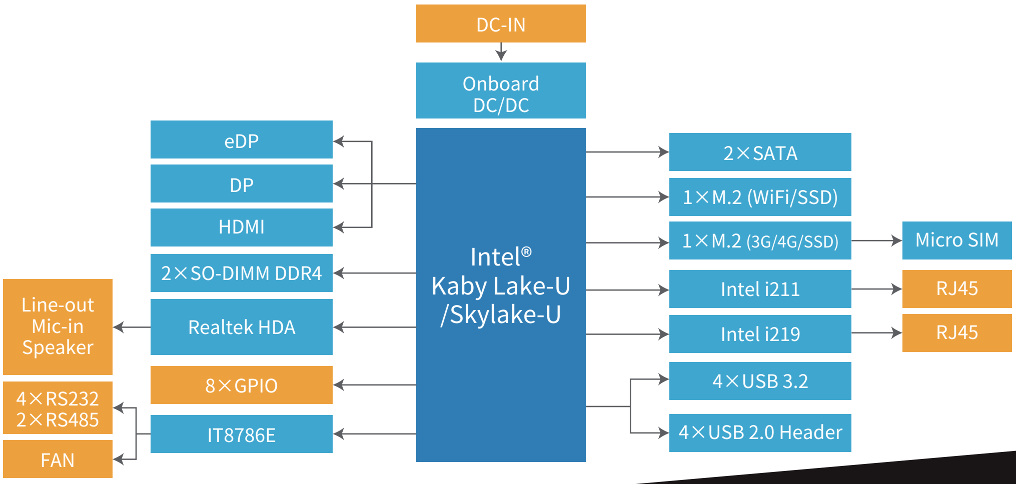
FEATURES

- CPU: Intel Skylake-U/Kaby Lake-U BGA Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 32GB
- I/O Interface: 2xLAN, 6xCOM(header), GPIO, 4xUSB3.2, 4xUSB2.0(header), LPC Optional, Audio,
- Display via: 1xHDMI, 1xDP, 1x eDP
- Storage: SATA3.0, M.2

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	3865U	i3 7100U	i5 7200U	i3 6100U	i5 6200U
Memory	SO-DIMM Dual channel DDR4-2133MHz, Max 32GB				
Storage	1×M.2 for 4G/2242 SSD, 2×SATA 3.0				
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×DP, 8×GPIO 1×eDP				
GPU	Intel HD Graphics				
Size	146mm×102mm				
Power	9~24V DC-in				
Temperature	-20°C~60°C				

SKD-70

Mini-ITX

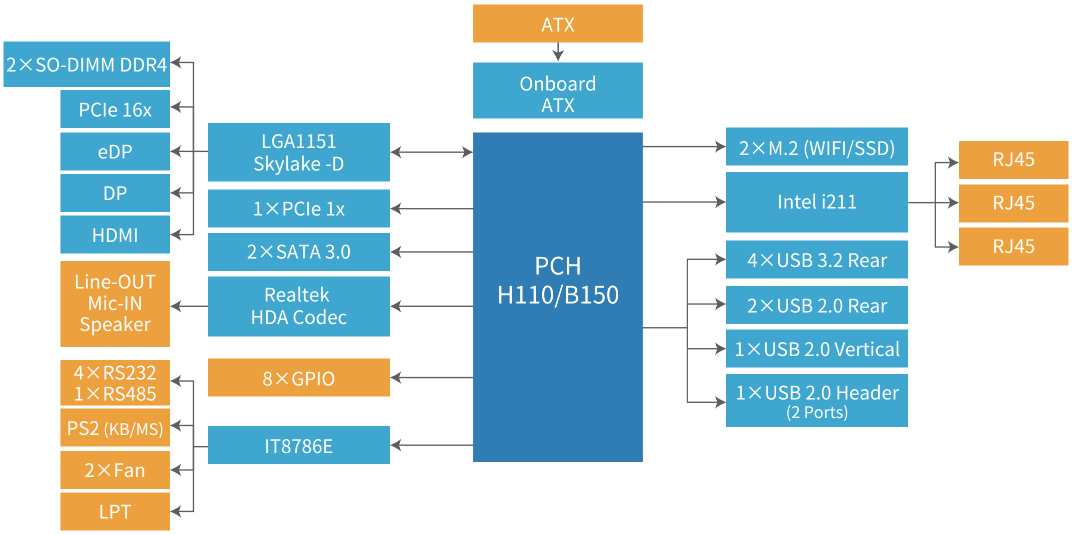
FEATURES

- CPU: Intel Skylake-S/Kaby Lake-S Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 32 GB
- I/O Interface: 3xLAN, 5xCOM(header), 4xUSB3.2, GPIO, LPT, 5xUSB2.0(2*header, 1*vertical interface), PS/2, Audio
- Display via: 1xHDMI, 1xDP,1x eDP Optional
- Storage: SATA3.0, M.2

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	Intel Skylake-S/Kaby Lake-S
Memory	Dual channel DDR4 SO-DIMM-2133/2400MHz, Max 32GB
Storage	2×SATA 3.0, 1×M.2 for 2242 SSD
I/O	3×LAN, 5×COM, 4×USB 3.2, 5×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×DP, 8×GPIO 1×eDP Optional
GPU	Intel HD Graphics
Size	170mm×170mm
Power	ATX_24V
Temperature	-20°C~60°C

SKD-75

ATX

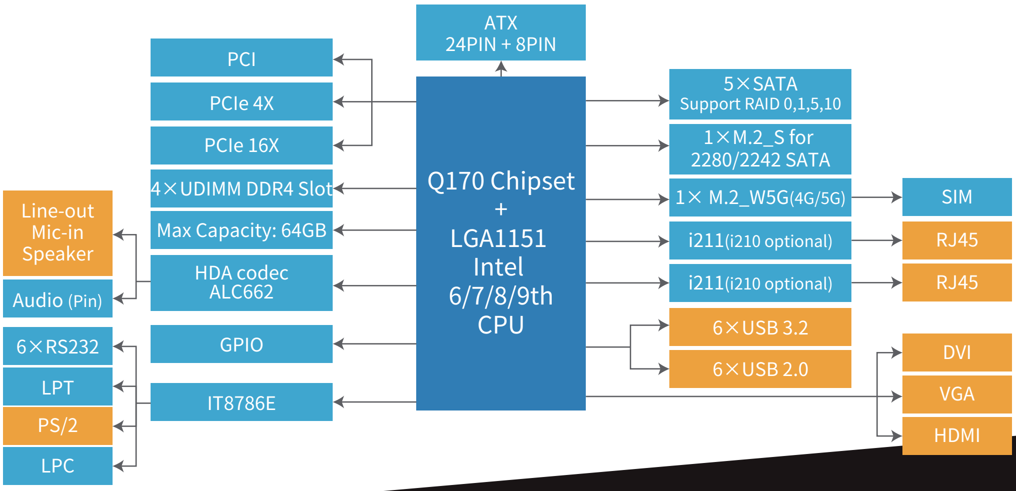
FEATURES

- CPU: Intel 6th,7th,8th,9th Gen Processor
- Memory: 4x UDIMM DDR4 up to 64GB
- I/O Interface: 2xLAN, 6xCOM(header), 6xUSB3.2(2*header), 6xUSB2.0(4*header), PS/2, GPIO, LPT, LPC, Audio,
- Display via: 1xHDMI, 1xVGA,1xDVI-D
- Storage: 5xSATA Support RAID 0,1,5,10, M.2

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES

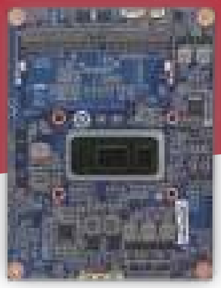


SPECIFICATIONS

CPU	Intel 6th/7th/8th/9th Gen
Memory	4×UDIMM DDR4, Max 64GB
Storage	1×M.2_S for 2280/2242 SATA, 1×M.2_E 2230 for Wi-Fi, 5×SATA
I/O Interface	2×LAN, 6×COM, 6×USB 3.2, 6×USB 2.0, 1×Mic in, 1×Line in, 1×Line out, 1×HDMI, 1×VGA 1×DVI, 1×GPIO, 1×LPT, 1×LPC
GPU	Intel HD/UHD Graphics
Size	305mm×244mm
Power	ATX_24V
Temperature	-20°C~60°C

WL-37

125 mm x 105.16 mm



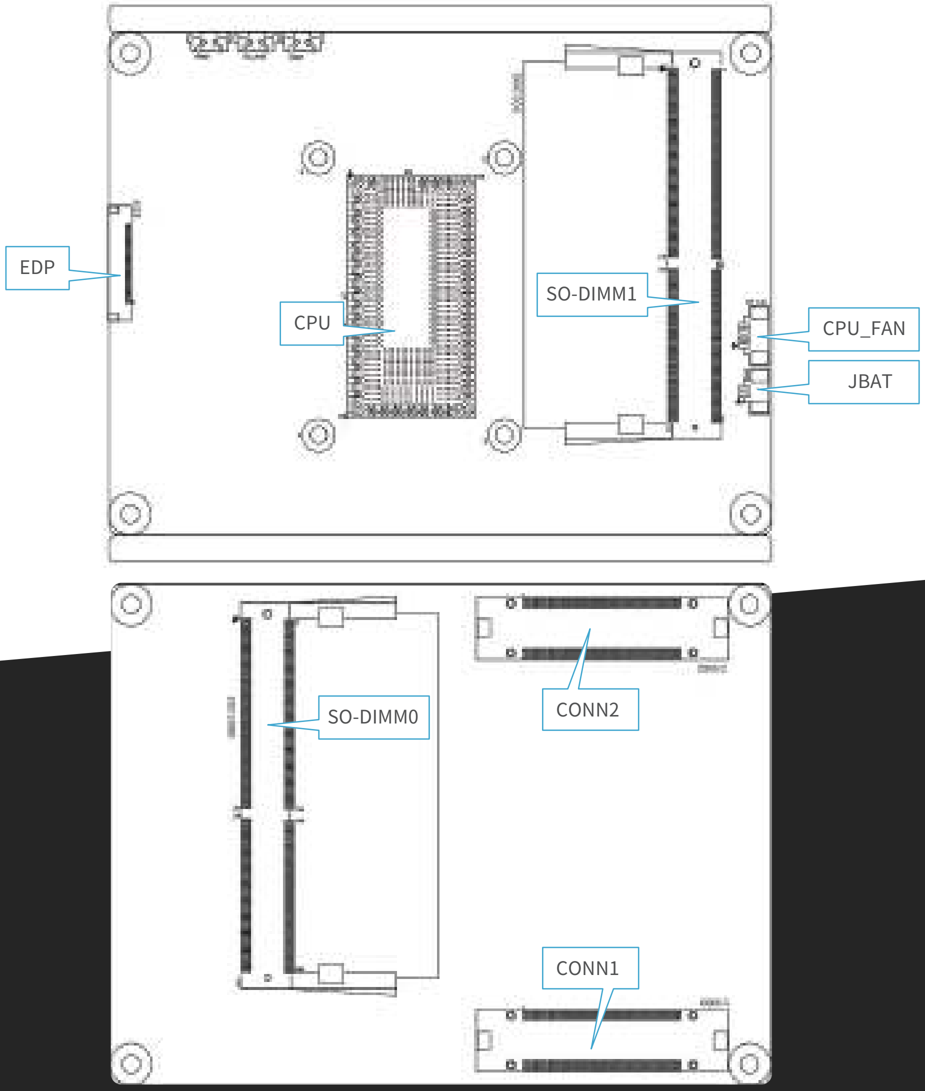
FEATURES

- CPU: Intel Whiskey Lake - U Celeron and Core Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64GB
- GPU: Integrated graphics, 1x eDP interface
- Other: 1x CONN1 and 1x CONN2 connectors
- Dimension: 125mm x 105.16 mm
- Power: 12V DC input

APPLICATIONS

- Phoenix Hill Industrial Module Kit
- Industrial Automation
- Manufacturing
- Edge Computing

I/O INTERFACES



TL-37

125 mm x 105.16 mm

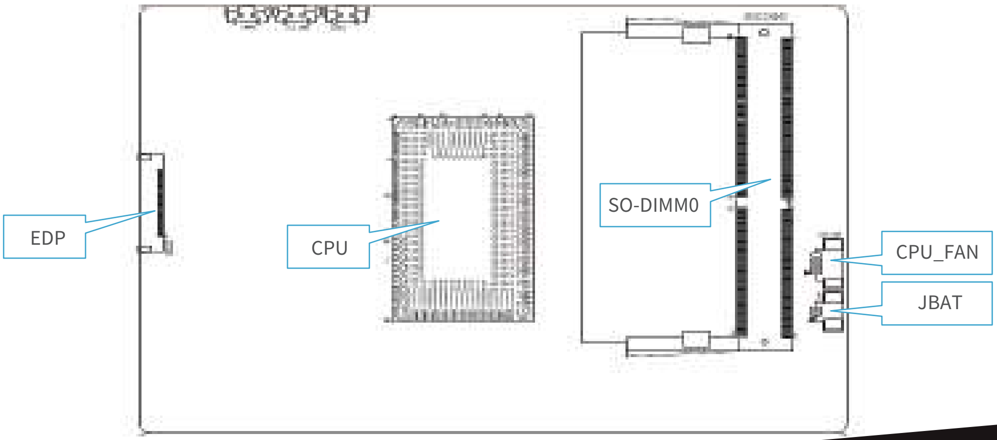
FEATURES

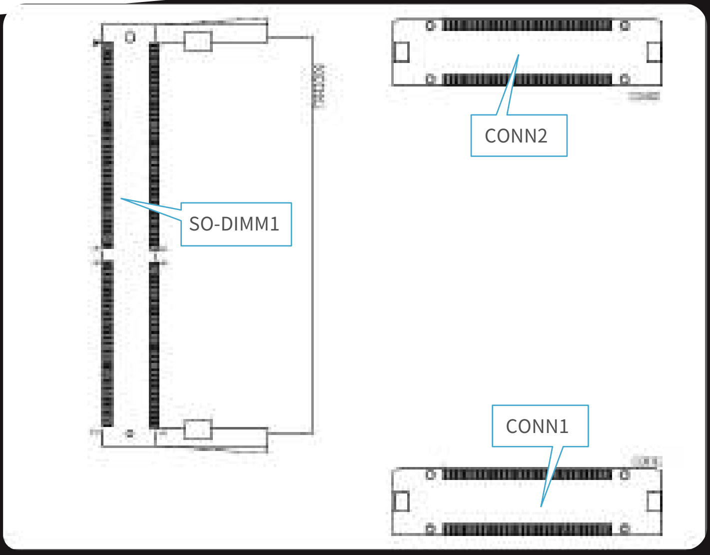
- CPU: Intel Tiger Lake-U Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64GB
- GPU: Integrated graphics, 1x eDP interface
- Other: 1x CONN1 and 1x CONN2 connectors
- Dimension: 125mm x 105.16 mm
- Power: 12V DC input

APPLICATIONS

- Phoenix Hill Industrial Module Kit
- Industrial Automation
- Manufacturing
- Edge Computing

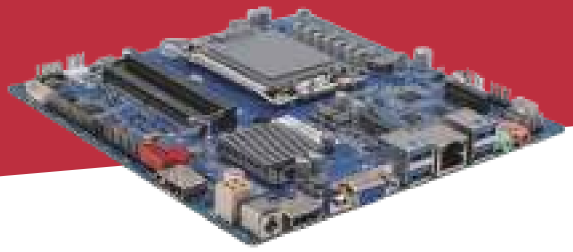
I/O INTERFACES





ALD-15

Mini-ITX



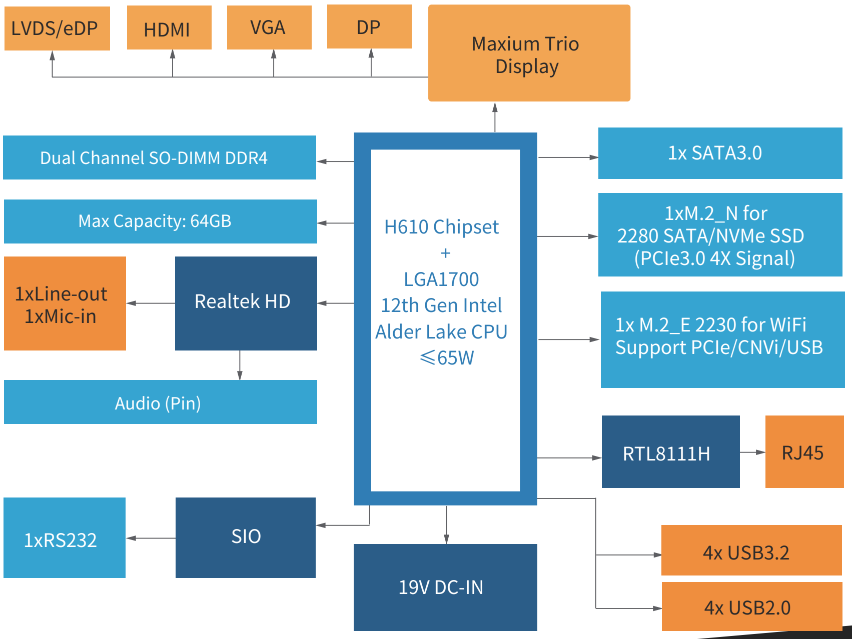
FEATURES

- CPU: 12th Gen Intel Core™,Celeron®and Pentium®Processor+H610
- Memory:Dual Channel SO-DIMM DDR4 up to 64GB
- Display: Integrated Graphics via DP,HDMI,LVDS/eDP,VGA
- Ethernet:10/100/1000 Mbps
- Storage:SATA3.0,M.2 for SATA/NVMe SSD (PICe4X Signal)
- Expansion: M.2 for WiFi,support PCle/CNVi/USB2.0
- Power: 19V DC input

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



LVDS/eDP

HDMI

VGA

DP

Maxium Trio Display

Dual Channel SO-DIMM DDR4

Max Capacity: 64GB

1xLine-out
1xMic-in

Realtek HD

Audio (Pin)

H610 Chipset
+
LGA1700
12th Gen Intel
Alder Lake CPU
≤65W

1x SATA3.0

1xM.2_N for
2280 SATA/NVMe SSD
(PCIe3.0 4X Signal)

1x M.2_E 2230 for WiFi
Support PCIe/CNVi/USB

RTL8111H

RJ45

1xRS232

SIO

19V DC-IN

4x USB3.2

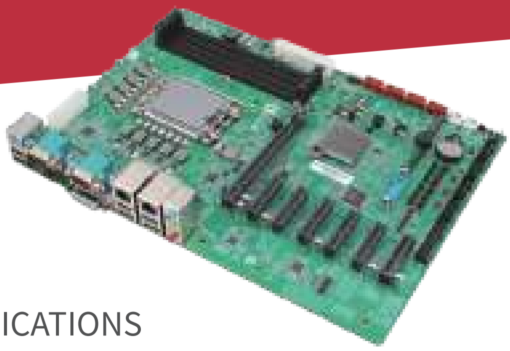
4x USB2.0

SPECIFICATIONS

CPU	12th Gen Intel® CoreTM i3/i5/i7/i9, Celeron® and Pentium® Proce ssor ≤65W
Memory	Dual Channel SO-DIMM DDR4
Storage	2×SATA 3.0, 1×M.2 for 2242 SSD
I/O Interface	1×LAN, 1×JCOM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out
GPU	Intel® Integrated graphics
Size	170mm x 170mm
Power	19V DC-in
Temperature	-40 ~ 80° C

ALD-75

ATX



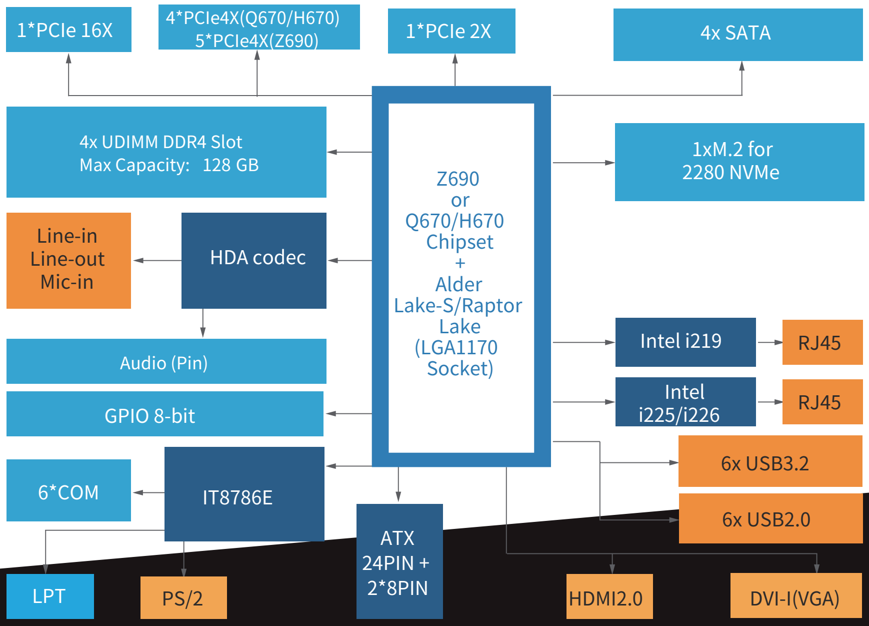
FEATURES

- CPU: Intel Alder Lake/Raptor Lake(LGA1700 Socket)
- Memory: 4x UDIMM DDR4 Up to 128GB
- Display: Integrated Graphics display via HDMI+DVI-I(VGA)
- Ethernet Controllers: 1xIntel i219+1xIntel i226
- Storage: 1xM.2 for NVMe SSD, 4xSATA
- Expansion: 1*PCIe2X, 1*PCIe16X, 5*PCIe4X(Z690) or 4*PCIe4X(Q670/H670)
- Power: ATX_24PIN + 2*8PIN

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES

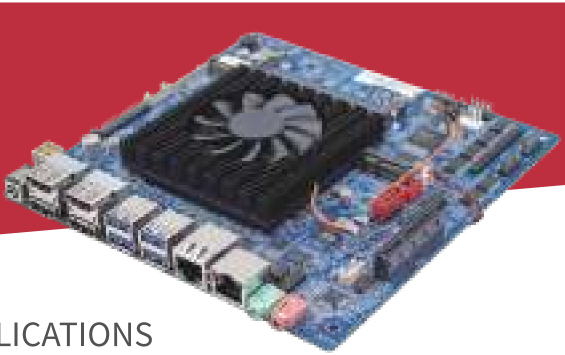


SPECIFICATIONS

CPU	Intel Alder Lake-S/Raptor Lake Processor (LGA1700)
Memory	4x UDIMM DDR4-3200
Storage	1x M.2_N 2280 for SATA/NVMe SSD (PCIe3.0 4X signal)
I/O Interface	2×LAN, 6×COM, 6×USB 3.2, 6×USB 2.0, 1×Mic in, 1×Line in, 1×Line out, 1×HDMI, 1×DVI, 1×GPIO, 1×LPT, 1×PS/2, 1×TPM2.0
GPU	Intel Integrated Graphics based on CPU
Size	304.8mm x 218.44mm
Power	ATX_24PIN + 2*8PIN
Temperature	-40 ~ 85° C

AL-10

Mini-ITX



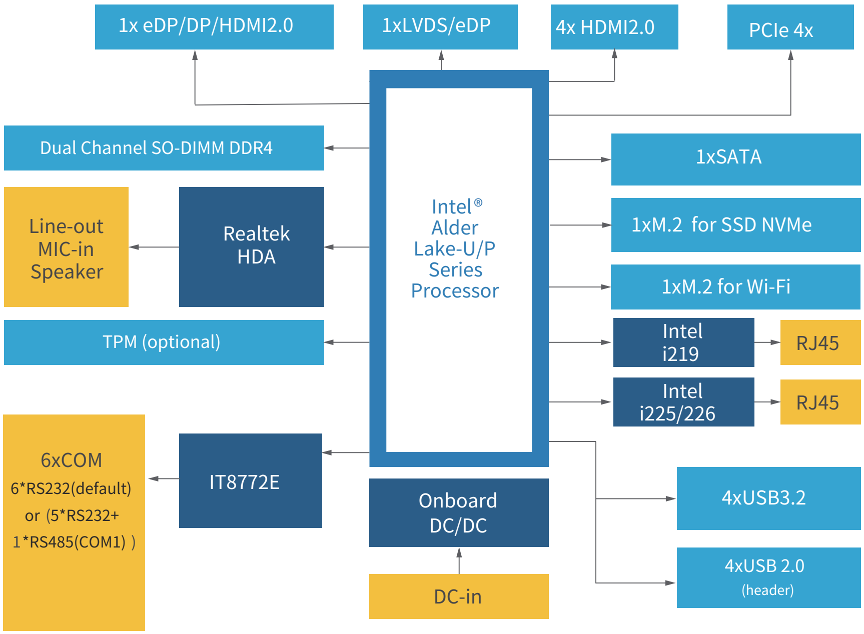
FEATURES

- CPU: Intel® Alder Lake-U/P series processor
- Memory: Dual channel SO-DIMM DDR4 up to 64GB
- GPU: Intel Iris® Xe Graphics eligible/UHD Graphics depends on CPU
- Ethernet Controller: Intel i225/i226 + Intel i219
- Storage: 1xM.2 for NVMe 2280 SSD, 1xSATA
- Expansion: M.2 for WiFi, PCIe 4X
- Power: 19V DC-in

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES

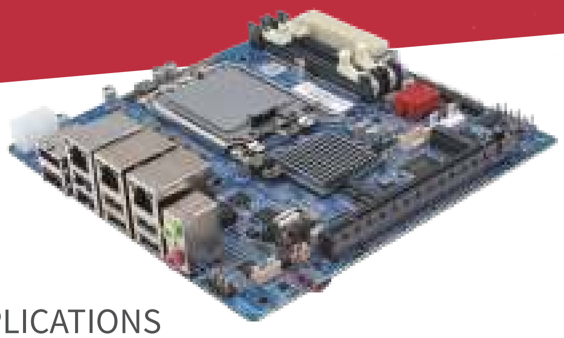


SPECIFICATIONS

CPU	i7-1260P	i5-1240P	i3-1220P
Memory	Dual Channel SO-DIMM DDR4		
Storage	1×M.2 for NVMe 2280 SSD		
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 8×GPIO 1×TPM2.0		
GPU	Intel Iris® Xe Graphics eligible/UHD Graphics depends on CPU		
Size	170mm×170mm		
Power	19V DC-in		
Temperature	-20°C~60°C		

ALD-70

Mini ITX



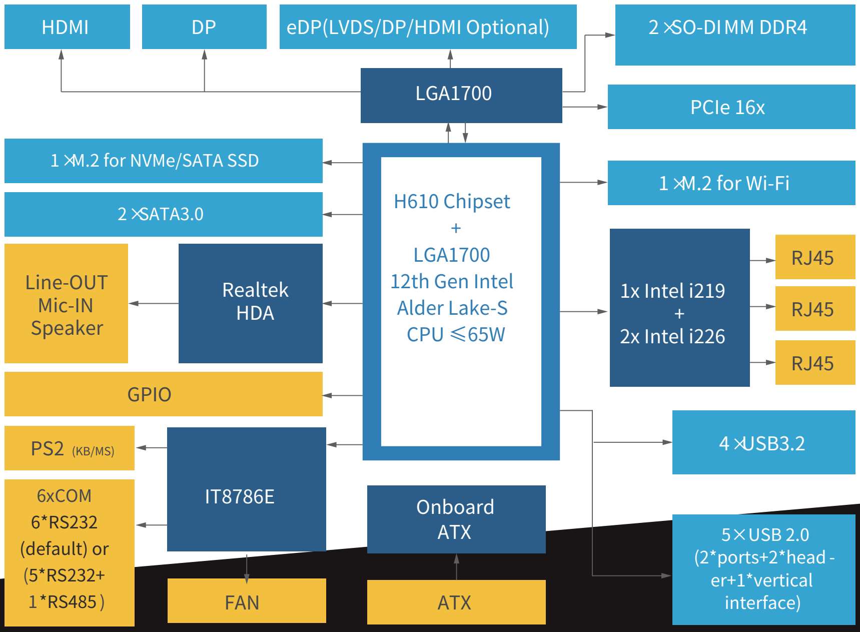
FEATURES

- CPU: 12th Generation Intel®CoreTM i3/i5/i7/i9 CPU+H610 Chipset
- Memory: Dual channel SO-DIMM DDR4 Up to 64GB
- Display: Integrated Graphics, display via DP+HDMI+eDP
- Ethernet Controllers: 1xInteli219+2xInteli226
- Storage: SATA3.0,M.2 for SSD
- Expansion: PCle 16X,M.2 for WiFi
- Power: ATX input

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



HDMI

DP

eDP(LVDS/DP/HDMI Optional)

2 ×SO-DIMM DDR4

LGA1700

PCle 16x

1 ×M.2 for NVMe/SATA SSD

2 ×SATA3.0

H610 Chipset
+
LGA1700
12th Gen Intel
Alder Lake-S
CPU ≤65W

1 ×M.2 for Wi-Fi

Line-OUT
Mic-IN
Speaker

Realtek
HDA

1x Intel i219
+
2x Intel i226

RJ45

RJ45

RJ45

GPIO

4 ×USB3.2

PS2 (KB/MS)

IT8786E

6xCOM
6*RS232
(default) or
(5*RS232+
1*RS485)

Onboard
ATX

5×USB 2.0
(2*ports+2*header+1*vertical interface)

FAN

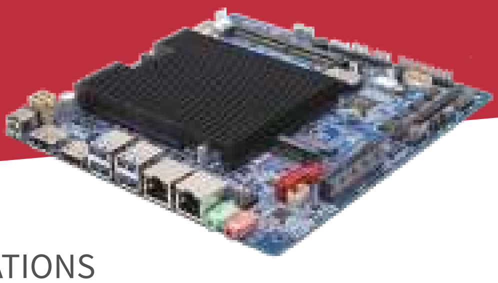
ATX

SPECIFICATIONS

CPU	i9-12900	i7-12700	i5-12400	i3-12300
Memory	Dual Channel SO-DIMM DDR4			
Storage	1x M.2 for 2280 NVMe/SATA SSD			
I/O Interface	3×LAN, 6×COM, 4×USB 3.2, 5×USB 2.0, 1×Mic in/Line out, 8×GPIO 1×PS/2, 1×TPM			
GPU	Integrated Intel®UHD graphics			
Size	170mm×170mm			
Power	24-pin ATX + 12V auxiliary ATX supply (2x4)			
Temperature	-40°C~80°C			

EHL-10

Mini-ITX



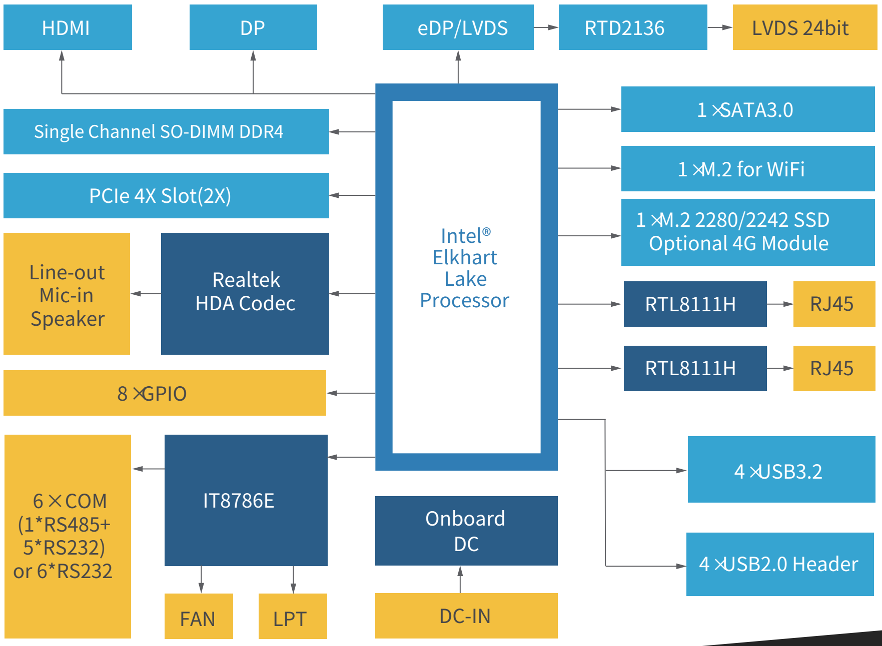
FEATURES

- CPU: Intel Elkhart Lake Celeron and Pentium processors
- Memory: Single channel SO-DIMM DDR4 up to 32GB
- Display: Intel UHD Graphics display via HDMI, DP, LVDS/eDP
- Ethernet: 10/100/1000 Mbps
- Storage: M.2 for 4G/SSD, SATA3.0
- Expansion: M.2 for WiFi, PCIe 4X(2X Signal), SIM optional

APPLICATIONS

- Industrial Automation
- Network Security
- Medical Equipment
- Surveillance
- Smart Transportation

I/O INTERFACES



SPECIFICATIONS

CPU	J6412	J6426	x6427FE	x6425RE
Memory	Single channel SO-DIMM DDR4 up to 32GB			
Storage	1×M.2 for 2280/2242 SSD, optional 4G Module			
I/O Interface	2xLAN, 6xCOM(header), 4xUSB3.2, 4xUSB2.0(header), GPIO, LPT, Audio, 1xHDMI+1xDP+1x LVDS/eDP			
GPU	Intel UHD Graphics for 10th Gen Intel Processors			
Size	170mm×170mm			
Power	12V DC-in /4 PIN Power			
Temperature	-20°C~60°C			

FP-20

Mini-ITX

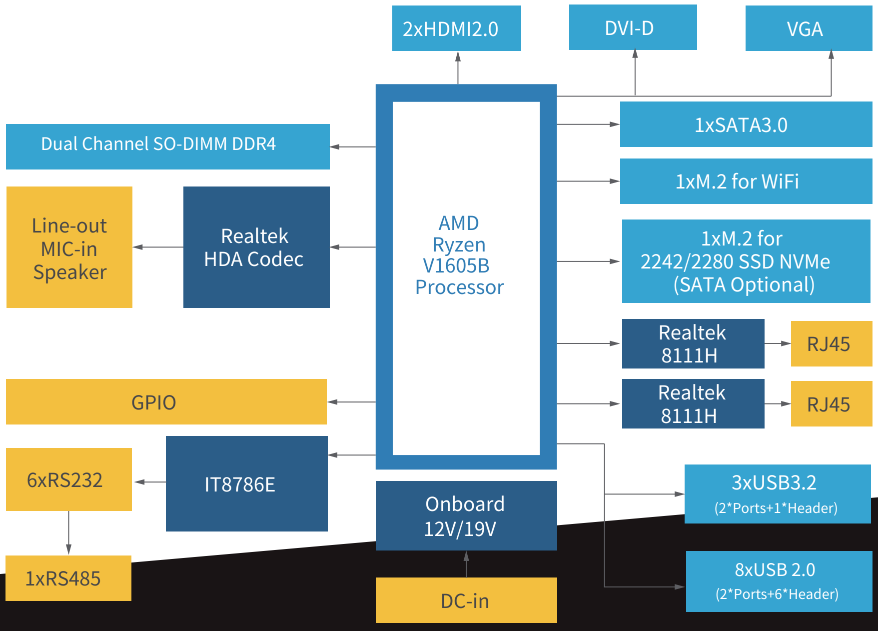
FEATURES

- CPU: Ryzen™ V1605B Quad Core Processor
- Memory: Dual channel SO-DIMM DDR4 up to 32 GB
- Display: Display via 2xHDMI2.0,1xDVI-D,1xVGA
- Ethernet: 10/100/1000Mbps
- Storage: SATA3.0, M.2 2242/2280 SSD NVME(SATA Optional)
- Expansion: 1xM.2 2230 for WiFi

APPLICATIONS

- Industrial Automation
- Medical Equipment
- Surveillance
- Digital Signage
- Smart Transportation

I/O INTERFACES

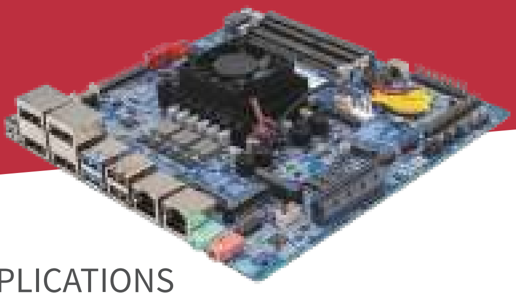


SPECIFICATIONS

CPU	V1605B (Quad-Core)
Memory	Dual Channel SO-DIMM DDR4, Max 32GB
Storage	1xM.2_Key M for 2242/2280 SSD NVMe (SATA Optional), SATA3.0
I/O Interface	2xLAN, 6xCOM(header), 3xUSB3.2(1*header) , 8xUSB2.0(6*header), GPIO, Audio, 2xHDMI2.0, DVI-D, VGA
GPU	Intel HD Graphics
Size	170mm×170mm
Power	12V DC-in
Temperature	-20°C~60°C

FP-610

Mini-ITX



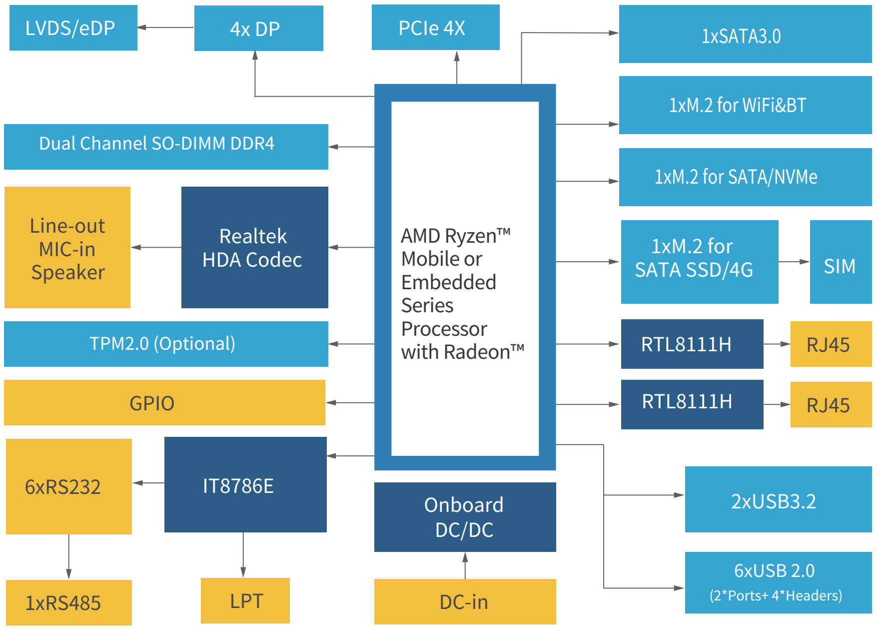
FEATURES

- CPU: AMD Ryzen™ Mobile/Embedded Series Processor
- Memory: Dual channel SO-DIMM DDR4 up to 64 GB
- Display: AMD Radeon™ Graphics, Up to 4 independent 4K displays
- Ethernet: 10/100/1000Mbps
- Storage: 1xSATA3.0, 2xM.2 for SSD
- Expansion: PCIe 4X, M.2 for WiFi

APPLICATIONS

- Medical Equipment, Surveillance
- Digital Signage
- Smart Transportation
- IoT Getaway

I/O INTERFACES

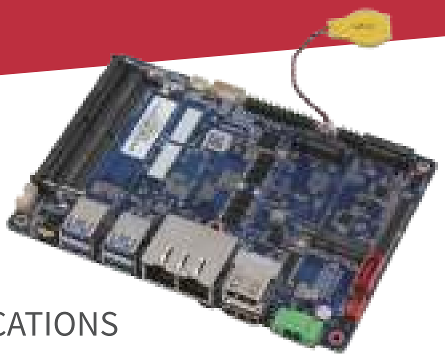


SPECIFICATIONS

CPU	V2516	5600H	5800H
Memory	Dual Channel SO-DIMM DDR4, Max 64GB		
Storage	SATA3.0, M.2 for SATA/4G, M.2 for NVMe/SATA		
I/O Interface	2xLAN, 6xCOM(header), 2xUSB3.2,6xUSB2.0(4*header), GPIO, LPT, Audio 4xDP1.4(DP1/LVDs/eDP optional)		
GPU	AMD Radeon™ Graphics		
Size	170 mm x 170 mm		
Power	19V DC-in		
Temperature	-20°C~60°C		

AL-35

3.5” Disk Size SBC



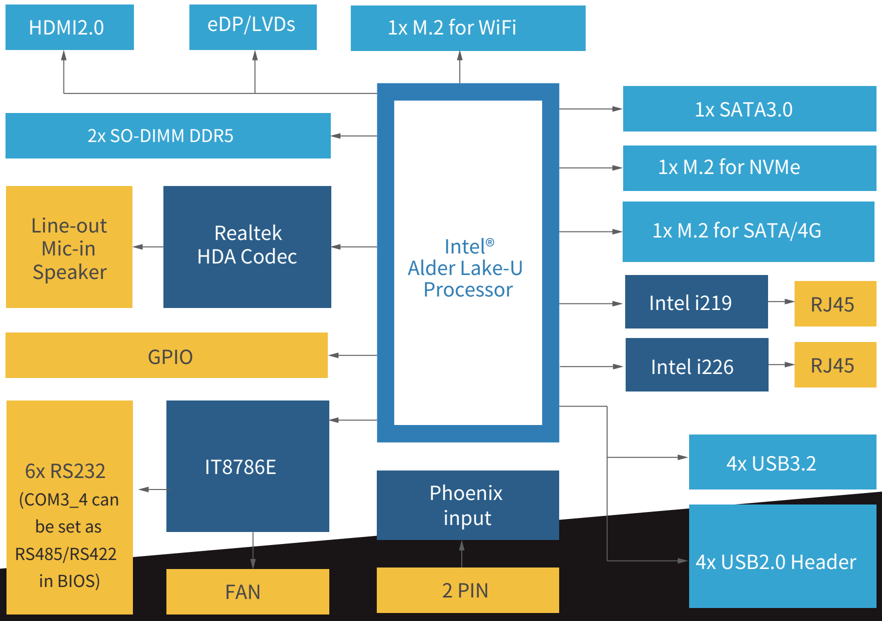
FEATURES

- CPU: Intel Alder Lake-U Processor
- Memory: Dual Channel SO-DIMM DDR5 up to 64GB
- Display: Integrated Graphics display via 2xHDMI, eDP/LVDs
- Ethernet: Intel i219(1.0G)+ Intel i226(2.5G)
- Storage: SATA, M.2 for SATA/4G, M.2 for NVMe
- Expansion: M.2 for WiFi

APPLICATIONS

- Industrial Automation
- Manufacturing
- Surveillance
- Digital Signage
- Smart Transportation

I/O INTERFACES



SPECIFICATIONS

CPU	i5-1235U
Memory	Dual Channel SO-DIMM DDR5, Max 64GB
Storage	SATA3.0, M.2 for SATA/4G, M.2 for NVMe
I/O Interface	2xLAN, 6xCOM(header), 4x USB3.2 ,4xUSB2.0(header), GPIO, Audio, 2xHDMI, 1x eDP/LVDs
GPU	Intel Integrated Graphics based on CPU
Size	146 mm x 102mm
Power	12V-35V Phoenix input (2Pin)
Temperature	-20°C~60°C

EHL-35

3.5” Disk Size SBC

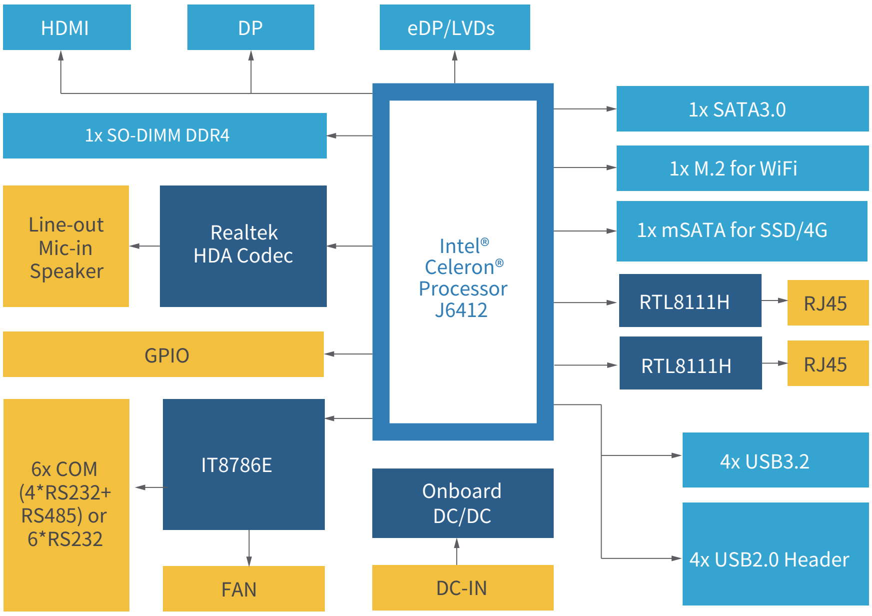
FEATURES

- CPU: Intel Celeron Processor J6412
- Memory: Single Channel SO-DIMM DDR4 up to 32GB
- Display: Integrated Graphics display via HDMI, DP, eDP/LVDs
- Ethernet: 10/100/1000 Mbps
- Storage: SATA3.0, mSATA
- Expansion: 1xM.2 for WiFi

APPLICATIONS

- Industrial Automation
- Manufacturing
- Surveillance
- Digital Signage
- Smart Transportation

I/O INTERFACES

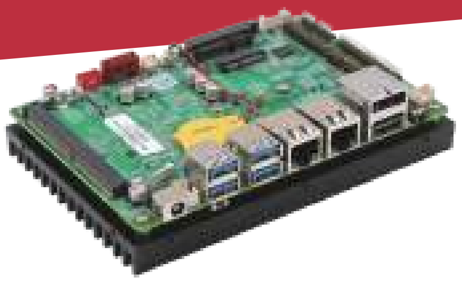


SPECIFICATIONS

CPU	Celeron J6412
Memory	Single Channel SO-DIMM DDR4, Max 32GB
Storage	1x mSATA for SSD/4G Module,1x SATA 2.5-inch HDD
I/O Interface	2xLAN, 6xCOM(header), GPIO, 4xUSB3.2, 4xUSB2.0(header), Audio,1xHDMI, 1xDP, 1x eDP/LVDs
GPU	Intel HD Graphics
Size	146mm×102mm
Power	12V DC-in
Temperature	-20°C~60°C

EHL-35V2.0

3.5” Disk Size SBC



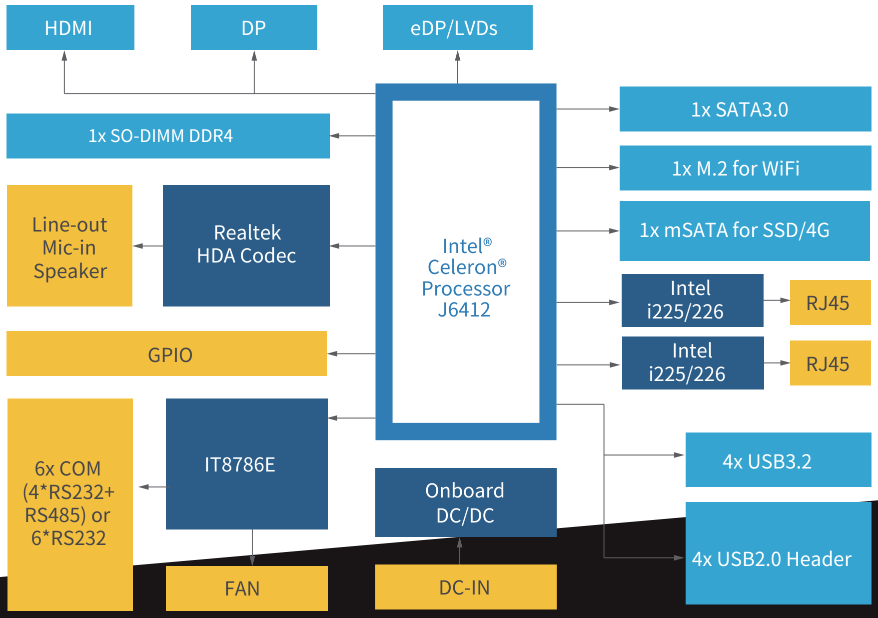
FEATURES

- CPU: Intel Celeron Processor J6412
- Memory: Single Channel SO-DIMM DDR4 up to 32GB
- Display: Integrated Graphics display via HDMI, DP, eDP/LVDs
- Ethernet: 10/100/1000/2500Mbps, 2xRJ45, Intel i225/226
- Storage: SATA3.0, mSATA
- Expansion: 1xM.2 for WiFi

APPLICATIONS

- Industrial Automation
- Manufacturing
- Surveillance
- Digital Signage
- Smart Transportation

I/O INTERFACES

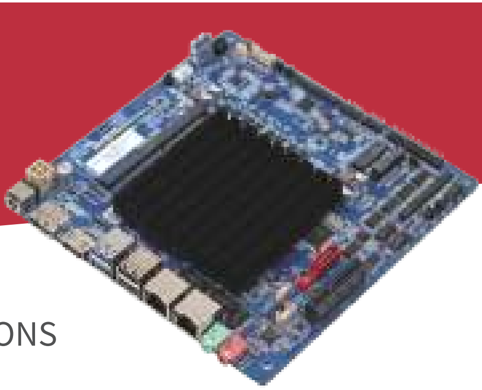


SPECIFICATIONS

CPU	Celeron J6412
Memory	Single Channel SO-DIMM DDR4, Max 32GB
Storage	1x mSATA for SSD/4G Module,1x SATA 2.5-inch HDD
I/O Interface	2xLAN, 6xCOM(header), GPIO, 4xUSB3.2, 4xUSB2.0(header), Audio,1xHDMI, 1xDP, 1x eDP/LVDs
GPU	Intel Integrated Graphics based on CPU
Size	146 mm x 102mm
Power	12V DC-in
Temperature	-20°C~60°C

ALN-10

Mini-ITX



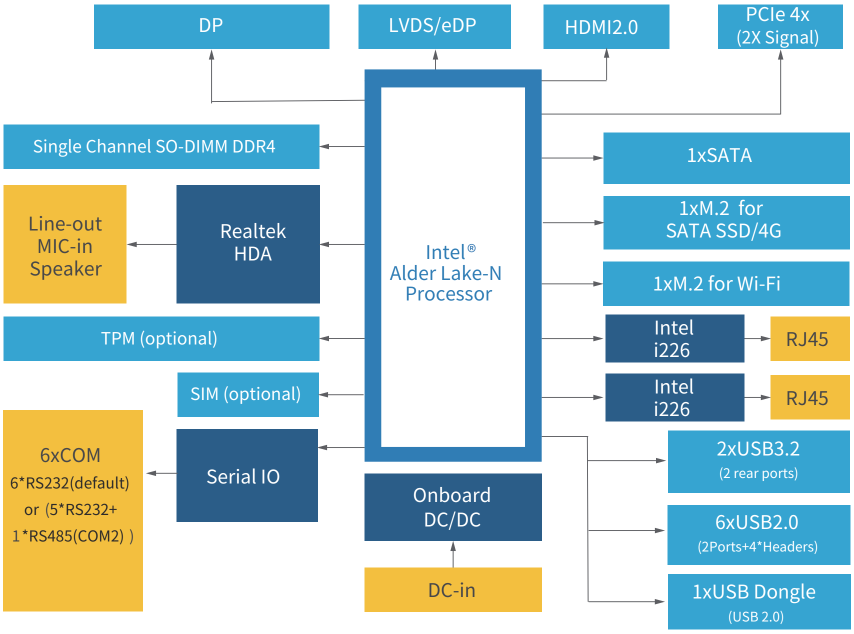
FEATURES

- CPU:Intel®Alder Lake-N Series processor
- Memory:Single channel SO-DIMM DDR4 up to 32GB
- GPU:Integrated Intel® UHD Graphics
- Ethernet Controller:Dual RJ45 Intel i226 2.5GbE
- Storage:1xM.2 for SATA SSD/4G,1xSATA
- Expansion:M.2 for WiFi,PCIe 4X(2X Signal)
- Power: 19V/12V DC-in

APPLICATIONS

- Digital Signage
- Industrial Automation
- POS/POI

I/O INTERFACES



SPECIFICATIONS

CPU	i3-N305	N300	N200	N100	N97	N50
Memory	Single Channel SO-DIMM DDR4					
Storage	1×M.2 for SATA SSD/4G					
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 8×GPIO 1×TPM2.0					
GPU	Intel Iris® Xe Graphics eligible/UHD Graphics depends on CPU					
Size	170mm×170mm					
Power	19V DC-in					
Temperature	-40°C~80°C					

EMBEDDED SYSTEM

(Industrial PC, OPS, Mini PC, Ultra Compact PC)

VBR-30

Fanless

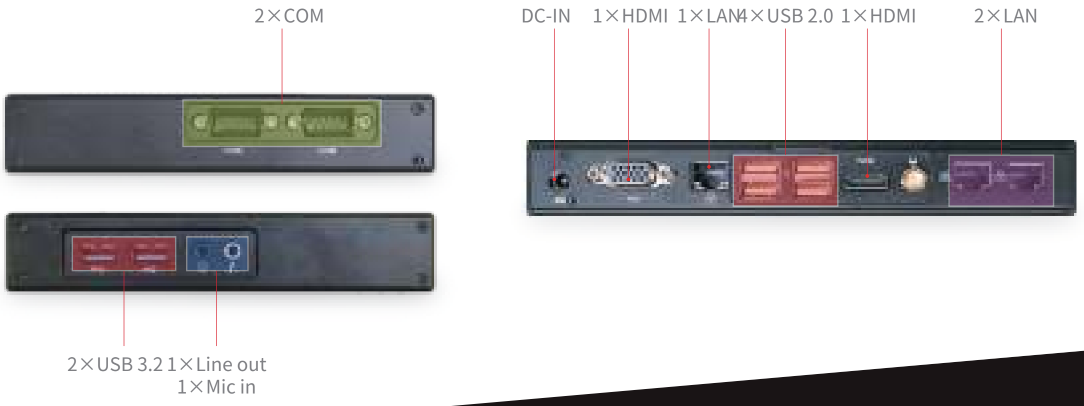
FEATURES

- CPU: Intel Braswell Processor
- Memory: 2x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 3xLAN, 2xCOM, 2xUSB3.2, 4x USB2.0
- Display via: 2x HDMI
- Storage: SATA, mSATA, eMMC optional
- Expansion: 1x Micro SIM slot, 1x mini-PCIe

APPLICATIONS

- Artificial Intelligence
- Automation
- Smart Transportation
- Medical

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron N3150	Celeron N3160
Memory	2×SO-DIMM DDR3L, Max 8GB	
Storage	1×mSATA, 1×SATA, 1×eMMC	
I/O Interface	3×LAN, 2×COM, 2×USB 3.2, 4×USB 2.0, 1×Mic in, 1×Line out, 2×HDMI	
GPU	Integrated Graphics	
Size	191mm×151mm×27mm	
Power	12/19V DC-in	
Temperature	-40°C~50°C	

VBYT-30

Fanless

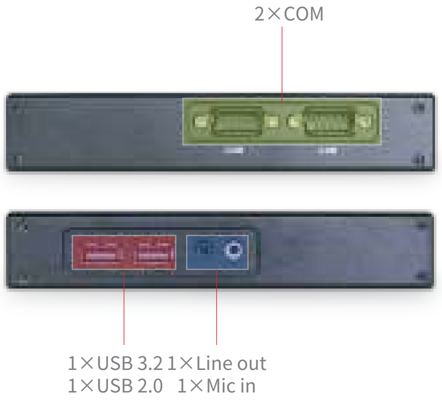
FEATURES

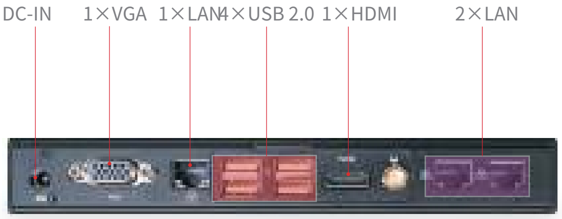
- CPU: Intel Bay Trail Processor
- Memory: 2x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 3xLAN, 2xCOM, 1xUSB3.2, 5x USB2.0
- Display via: VGA, HDMI
- Storage: SATA, mSATA
- Expansion: 1x SIM Card Slot, 1x mini-PCIe(for WiFi or 3G/4G)

APPLICATIONS

- Artificial Intelligence
- Automation
- Smart Transportation
- Medical

I/O INTERFACES





SPECIFICATIONS

CPU	J1800	J1900	N2940	E3845
Memory	2×SO-DIMM DDR3L, Max 8GB			
Storage	1×mSATA, 1×SATA 3.0			
I/O Interface	3×LAN, 2×COM, 1×USB 3.2, 5×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×VGA			
GPU	Integrated Graphics			
Size	150mm×190mm×29mm			
Power	12/19V DC-in			
Temperature	-20°C~ 50°C			

VBYT-31

Fanless

FEATURES

- CPU: Intel Bay Trail Processor
- Memory: 1x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 6xLAN, 1xCOM (Default RS232), 4x USB2.0
- Display via: VGA
- Storage: SATA, mSATA
- Expansion: 1x SIM Card slot, 1x mini-PCIe(for WiFi or 3G/4G)

APPLICATIONS

- Artificial Intelligence
- Automation
- Smart Transportation
- Medical

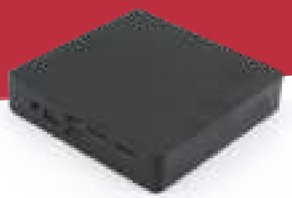
I/O INTERFACES

SPECIFICATIONS

CPU	Celeron J1800	Celeron J1900
Memory	1×SO-DIMM DDR3L, Max 8GB	
Storage	1×mSATA, 1×SATA 3.0	
I/O Interface	6×LAN, 4×USB 2.0, 1×VGA, 1×COM	
GPU	Integrated Graphics	
Size	150mm×190mm×29mm	
Power	9~24V DC-in	
Temperature	-20°C~ 60°C	

DBYT-50

Fanless



FEATURES

- CPU: Intel Bay Trail Processor
- Memory: 1x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 1xLAN, 1xUSB3.2, 4x USB2.0,
- Display via: 1x mini-HDMI, 1x VGA
- Storage: mSATA, eMMC Optional
- Expansion: 1x Mini PCIe for WiFi, 1xSIM, 1xTF

APPLICATIONS

- Network Security
- Automation
- Communication
- Transportation

I/O INTERFACES

SPECIFICATIONS

CPU	Celeron J1800	Celeron J1900	Celeron N2808
Memory	1×DDR3L-1333MHz, Max 8GB		
Storage	1×mSATA, 1×eMMC, 1×TF 卡槽		
I/O Interface	1×LAN, 1×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×Mini HDMI, 1×VGA		
GPU	Intel HD Graphics		
Size	127mm×127mm×25mm		
Power	19V DC-in		
Temperature	-15°C~65°C		

VHWL-30

Fanless

FEATURES

- CPU: Intel Whiskey Lake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 2xLAN, 1xCOM ,2x USB3.2, 4x USB2.0
- Display via: DP, HDMI & mini HDMI
- Storage: 1x M.2 2280 SSD (NVMe),1x M.2 2240 SSD or 3G/4G
- Expansion: 1x SIM slot, 1x M.2 for WiFi)

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

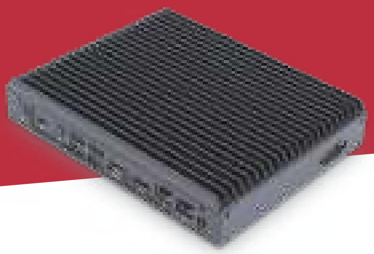
I/O INTERFACES

SPECIFICATIONS

CPU	Celeron 4205U	i3 8145U	i5 8265U
Memory	2×SO-DIMM DDR4-2400MHz, Max 64GB		
Storage	1×M.2 for 4G or 2242 SSD, 1×M.2 for 2280 NVMe SSD		
I/O Interface	2×LAN, 1×COM, 1×SIM, 2×USB 3.2, 4×USB 2.0, 1×Line out, 1×Mic in, 1×HDMI, 1×Mini HDMI, 1×DP		
GPU	Intel UHD Graphics 610/620		
Size	191mm×151mm×34mm		
Power	19V DC-in		
Temperature	-20°C~ 60°C		

VHKL-30

Fanless



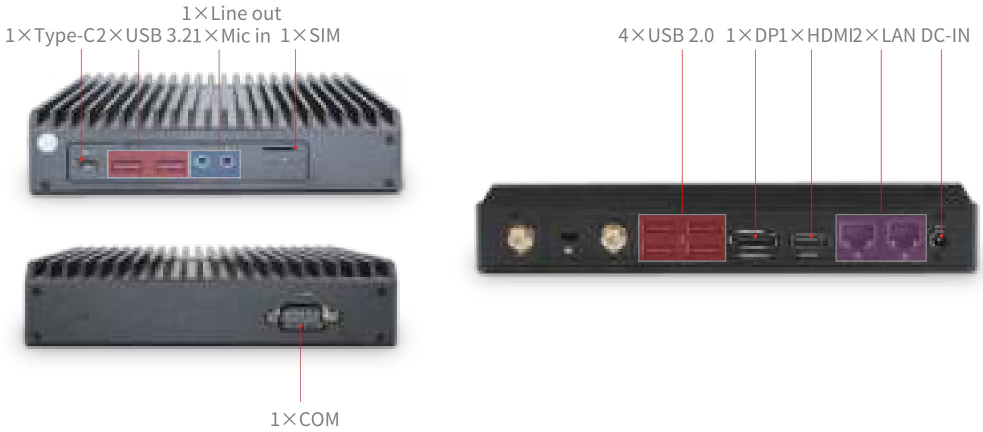
FEATURES

- CPU: Intel KabyLake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 32 GB
- I/O Interface: 2xLAN, 1xCOM, 2xUSB3.2, 4x USB2.0,USB-C
- Display via: HDMI, DP
- Storage: 1x M.2 2280 SSD,1x M.2 2240 SSD or 3G/4G
- Expansion: 1x M.2 for WiFi, 1x SIM slot

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

I/O INTERFACES



SPECIFICATIONS

CPU	3865U	i3 7100U	i5 7200U	i7 7500U
Memory	2×DDR4-2133MHz, Max 32GB			
Storage	1×2242 SSD or 4G, 1×2242/2280 SSD			
I/O Interface	2×LAN, 1×COM, 1×SIM, 2×USB 3.2, 4×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI 1×DP, 1×USB-C			
GPU	Integrated Graphics			
Size	191mm×151mm×34mm			
Power	19V DC-in			
Temperature	-20°C~60°C			

VHHM-10

Fanless

FEATURES

- Aluminum enclosure
- Intel Broadwell processor
- Single channel DDR3L-1600MHz up to 8GB
- mSATA interface for SSD, wifi, 4G module
- Embedded, VESA mount and desktop ready for easy installation
- Fanless design and low power consumption

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

I/O INTERFACES

SPECIFICATIONS

CPU	i3 5010U	i5 5200U	
Memory	1×DDR3L-1600MHz, Max 8GB		
Storage	1×mSATA for SSD, 1×SATA 3.0		
I/O Interface	2×LAN, 1×COM, 2×USB 3.2, 4×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×Mini HDMI		
GPU	Intel HD Graphics		
Size	191mm×151mm×34mm		
Power	19V DC-in		
Temperature	-20°C~60°C		

VHBYT-30

Fanless

FEATURES

- CPU: Intel Bay Trail Processor
- Memory: 2x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 3xLAN, 2xCOM, 1xUSB3.2, 5x USB2.0
- Display via: HDMI, VGA
- Storage: SATA3.0, mSATA
- Expansion: 1x SIM Card Slot, 1x mini-PCIe(for WiFi or 3G/4G)

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

I/O INTERFACES

SPECIFICATIONS

CPU	J1800	J1900	N2940	E3845
Memory	2×SO-DIMM DDR3L, Max 8GB			
Storage	1×SATA 3.0, 1×mSATA			
I/O Interface	3×LAN, 2×COM, 1×USB 3.2, 5×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×VGA			
GPU	Intel HD Graphics			
Size	150mm×190mm×29mm			
Power	12/19V DC-in			
Temperature	-20°C~50°C			

VAPL-30

Fanless

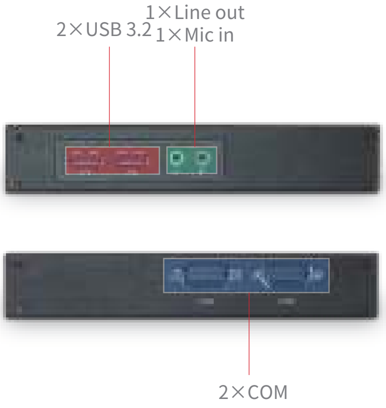
FEATURES

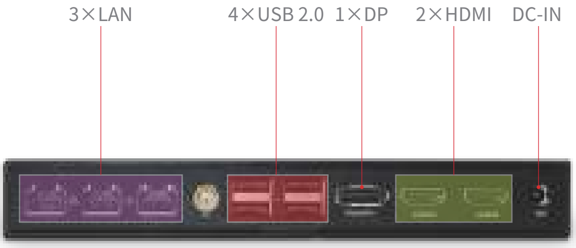
- CPU: Intel Apollo Lake Processor
- Memory: 2x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 3xLAN, 2xCOM, 2xUSB3.2, 4x USB2.0
- Display via: 2x HDMI, 1x DP
- Storage: SATA, mSATA, eMMC Optional
- Expansion: 1x Micro SIM slot, 1x mini-PCIe

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

I/O INTERFACES——





SPECIFICATIONS——

CPU	J3355	J3455	N3450	J4205
Memory	2 ×DDR3L-1600MHz, Max 8GB			
Storage	1×mSATA for SSD, 1×SATA			
I/O Interface	3×LAN, 2×COM, 2×USB 3.2, 4×USB 2.0, 1×Mic in, 1×Line out, 2×HDMI, 1×DP			
GPU	Integrated Graphics			
Size	191mm×151mm×27mm			
Power	12/19V DC-in			
Temperature	-20°C~60°C			

VFFP-30

Smart Fan

FEATURES

- CPU: Ryzen™ 5 2500U, 3500U and V1605B Processor
- Memory: 2x SO-DIMM DDR4 up to 32 GB
- I/O Interface: 2xLAN, 1xCOM, 2xUSB3.2, 4x USB2.0, USB-C
- Display via: DP, HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: 1x M.2 2280 SSD, 1x M.2 2242 SSD or 3G/4G

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

I/O INTERFACES

SPECIFICATIONS

CPU	AMD 2500U	AMD V1605B	
Memory	2×SO-DIMM DDR4, Max 32GB		
Storage	1×M.2 for 2280 NVMe SSD, 1×M.2 for 2242 SSD or 4G		
I/O Interface	2×LAN, 1×COM, 1×SIM, 2×USB 3.2, 4×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI 1×DP, 1×Type-c, 1×SIM		
GPU	AMD Radeon Vega 8 Graphics		
Size	191mm×151mm×27mm		
Power	12V DC-in		
Temperature	0°C~60°C		

FX1605

Smart Fan

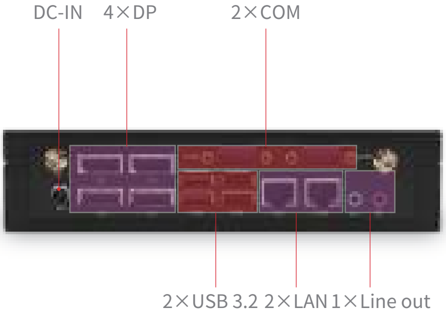
FEATURES

- CPU: AMD Ryzen V1605B Processor
- Memory: 2x SO-DIMM DDR4 up to 32 GB
- I/O Interface: 2xLAN, 2xCOM, 2xUSB3.2, 4x USB2.0
- Display via: 4x DP,
- Ethernet: 10/100/1000 Mbps
- Storage: SATA3.0, 1x M.2 for 2242/2280 SSD or 4G

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

I/O INTERFACES



SPECIFICATIONS

CPU	AMD V1605B
Memory	2×SO-DIMM DDR4, Max 32GB
Storage	1×M.2 for 4G/2280 SSD, 1×SATA 3.0
I/O Interface	2×LAN, 2×COM, 2×USB 3.2, 4×USB 2.0, 2×Mic in, 2×Line out, 4×DP
GPU	AMD Radeon Vega 8 Graphics
Size	205mm×190mm×45mm
Power	12V DC-in
Temperature	-20°C~60°C

IXKL-35

Fanless

FEATURES

- CPU: Intel Skylake-U/Kabylake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 32 GB
- I/O Interface: 2xLAN, 6xCOM ,4x USB3.2, 4x USB2.0
- Display via: DP, HDMI
- Storage: 1x M.2 2240 SSD or 4G, SATA3.0
- Expansion: 1x M.2 for WiFi, 1x SIM slot

APPLICATIONS

- Digital Signage
- POS Systems
- Power and Energy
- Logistics

I/O INTERFACES

SPECIFICATIONS

CPU	Celeron 3855U	i3 7100U	i5 7200U
Memory	2×SO-DIMM DDR4, Max 32GB		
Storage	1×M.2 2242 for SSD or 4G, 1×SATA 3.0		
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×DP		
GPU	Integrated Graphics		
Size	165mm×125mm×65mm		
Power	9~24V DC-in		
Temperature	-20°C~60°C		

IXBYT-35

Fanless

FEATURES

- CPU: Intel Bay Trail Processor
- Memory: Single Channel SO-DIMM DDR3L up to 8 GB
- I/O Interface: 2xLAN, 6xCOM, 1xUSB3.2, 7x USB2.0
- Display via: HDMI, VGA
- Storage: SATA2.0, mSATA,
- Expansion: 1x mini PCIe for WiFi/4G, 1x SIM slot

APPLICATIONS

- Manufacturing
- Rail Transportation
- New Energy

I/O INTERFACES

SPECIFICATIONS

CPU	J1900	J1800	N2940
Memory	Onboard 4GB, Max 4GB		
Storage	1×mSATA for SSD, 1×SATA 2.0		
I/O Interface	2×LAN, 6×COM, 1×USB 3.2, 5×USB 2.0, 1×HDMI, 1×VGA		
GPU	Intel HD Graphics		
Size	165mm×125mm×65mm		
Power	12V DC-in		
Temperature	-40°C~60°C		

IXAPL-35

Fanless

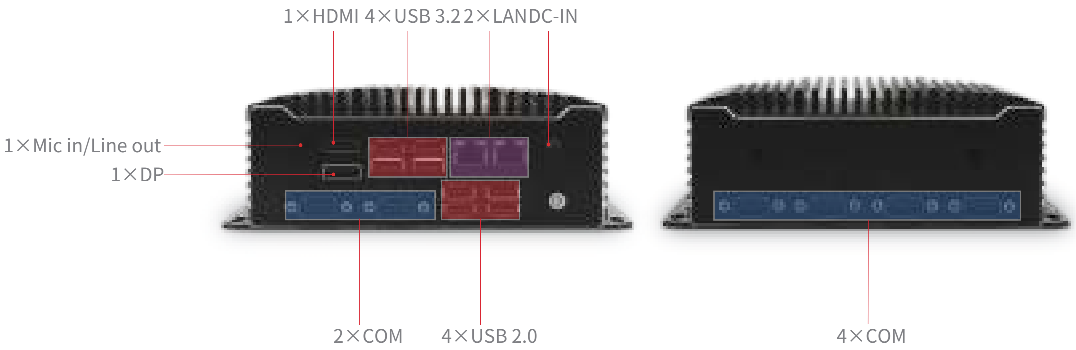
FEATURES

- CPU: Intel Apollo Lake Processor
- Memory: 1x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 2xLAN, 6xCOM ,4x USB3.2, 4x USB2.0
- Display via: DP, HDMI
- Storage: 1x M.2 2240 SSD or 4G, SATA3.0,
- Expansion: 1x M.2 for WiFi

APPLICATIONS

- Digital Signage
- POS Systems
- Power and Energy
- Logistics

I/O INTERFACES



SPECIFICATIONS

CPU	N3450	J3455	J4205
Memory	1×SO-DIMM DDR3L, Max 8GB		
Storage	1×M.2 2242 for SSD or 4G, 1×SATA 3.0		
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 4×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×DP		
GPU	Intel Integrated Graphics		
Size	165mm×125mm×65mm		
Power	9~24V DC-in		
Temperature	-40°C~60°C		

IXBW-35

Fanless

FEATURES

- CPU: Intel Broadwell/Haswell-U Processor
- Memory: 1x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 2xLAN, 6xCOM, 3xUSB3.2, 5x USB2.0
- Display via: HDMI, DP, VGA optional
- Storage: SATA3.0, mSATA(4G optional)
- Expansion: 1x M.2 for WiFi

APPLICATIONS

- Manufacturing
- Rail Transportation
- New Energy

I/O INTERFACES

SPECIFICATIONS

CPU	i5 4200U	i3 5005U	i5 5200U
Memory	1×DDR3L-1600MHz, Max 8GB		
Storage	1×mSATA, 1×SATA 3.0		
I/O Interface	2×LAN, 6×COM, 3×USB 3.2, 5×USB 2.0, 1×Mic in/Line out, 1×HDMI, 1×DP		
GPU	Intel HD Graphics		
Size	165mm×125mm×65mm		
Power	12V DC-in		
Temperature	-20°C~60°C		

AXKL-10

Fanless

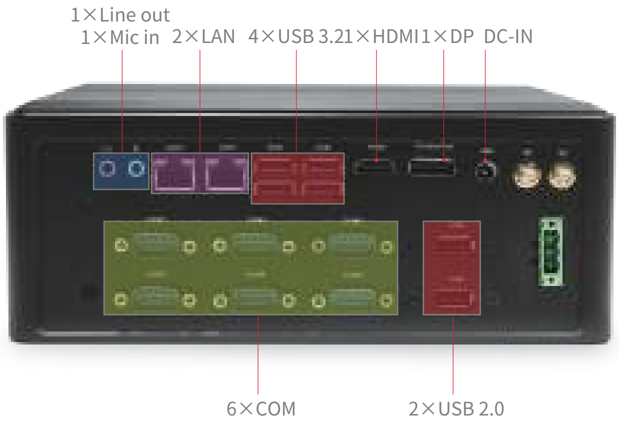
FEATURES

- CPU: Intel Kabylake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 32 GB
- I/O Interface: 2xLAN, 6xCOM, 4x USB3.2, 4x USB2.0
- Display via: DP, HDMI
- Storage: SATA3.0, 1x M.2 for 2242 SSD
- Expansion: 1x M.2 for WiFi, 1x M.2 for 4G

APPLICATIONS

- Artificial Intelligence
- Automation
- Rail Transportation
- Medical

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 3865U	i3 7100U	i5 7200U
Memory	2×DDR4-2133MHz, Max 32GB		
Storage	1×SATA 3.0, 1×M.2 for 2242 SSD		
I/O Interface	2×LAN, 6×COM, 4×USB 3.2, 2×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×DP		
GPU	Intel HD Graphics		
Size	225.5mm×190mm×74mm		
Power	12V DC-in		
Temperature	-15°C~50°C		

AXWL-10

Fanless

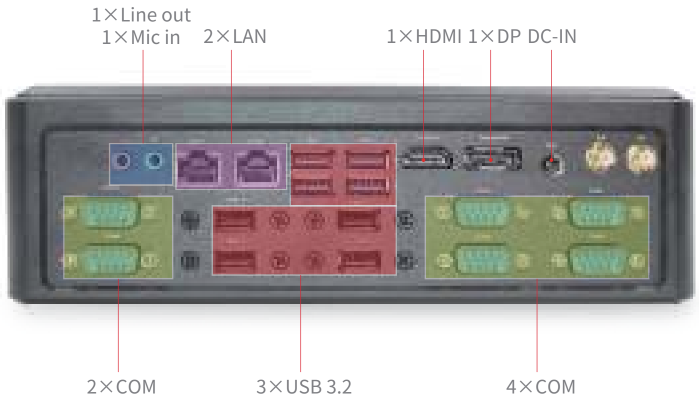
FEATURES

- CPU: Intel Whiskey Lake/Comet Lake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 2xLAN, 6xCOM, 3xUSB3.2, 5xUSB2.0
- Display via: DP, HDMI
- Storage: 1x M.2 for SSD/4G, SATA3.0
- Expansion: 1x M.2 for WiFi

APPLICATIONS

- Artificial Intelligence
- Automation
- Rail Transportation
- Medical

I/O INTERFACES——接口



SPECIFICATIONS——

CPU	Celeron 4205U	i3 8145U	i5 8265U	i7 8665U
Memory	2×DDR4-2400MHz, Max 64GB			
Storage	1×M.2 for 4G/SSD , 1×SATA 3.0			
I/O Interface	2×LAN, 6×COM, 3×USB 3.2, 5×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×DP			
GPU	Intel UHD Graphics 610/620			
Size	225.5mm×190mm×74mm			
Power	12V DC-in			
Temperature	-20°C~60°C			

AXBYT-60

Fanless

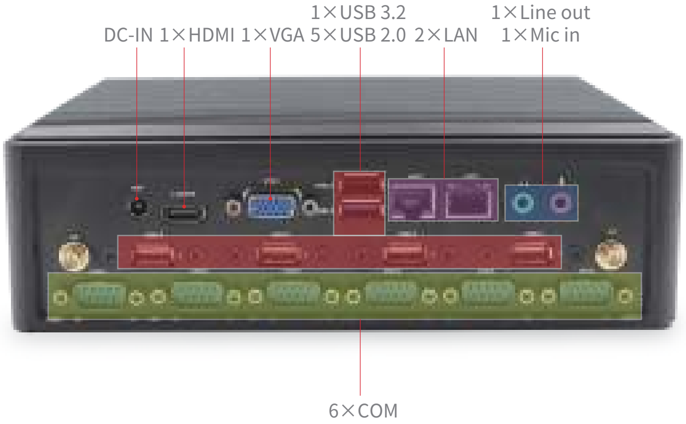
FEATURES

- CPU: Intel Bay Trail Processor
- Memory: 1x SO-DIMM DDR3L up to 8 GB
- I/O Interface: 2xLAN, 6xCOM, 1xUSB3.2, 5x USB2.0
- Display via: VGA, HDMI
- Storage: SATA2.0, mSATA
- Expansion: 1x mini PCIe for WiFi/3G/4G

APPLICATIONS

- Artificial Intelligence
- Automation
- Smart Transportation
- Medical

I/O INTERFACES



SPECIFICATIONS

CPU	J1800	J1900	
Memory	1×DDR3L-1333MHz, Max 8GB		
Storage	1×mSATA, 2×SATA 2.0		
I/O Interface	2×LAN, 6×COM, 1×USB 3.2, 5×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×VGA		
GPU	Intel HD Graphics		
Size	225.5mm×190mm×70mm		
Power	12V DC-in		
Temperature	-20°C~60°C		

IXWL-35

Fanless

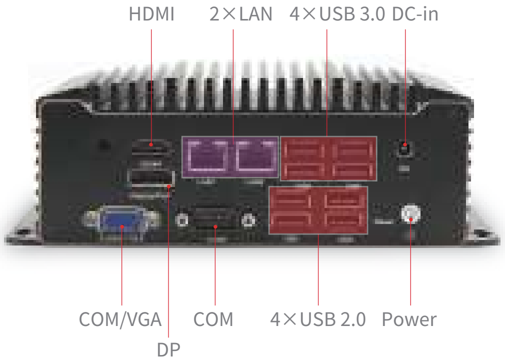
FEATURES

- CPU: Intel Whiskey Lake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 2xLAN, 6xCOM, 4xUSB3.2, 4x USB2.0
- Display via: HDMI, DP, VGA optional
- Ethernet: 10/100/1000 Mbps
- Storage: SATA3.0, 1x M.2 2240 SSD or 4G
- Expansion: 1x M.2 for WiFi

APPLICATIONS

- igital Signage
- POS Systems
- Power and Energy
- Logistics

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 4205U	i3-8145U	i5-8265U
Memory	Dual Channel SO-DIMM DDR4, Max 64GB		
Storage	1×M.2 for 4G/2242 SSD, 1×SATA 3.0, 1×M.2 for Wi-Fi		
I/O Interface	2×LAN, 4×USB 3.0, 4×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×DP, 6×COM		
GPU	Intel UHD Graphics		
Size	165mm×125mm×65mm		
Power	12/19V DC_in		
Temperature	-20°C~60°C		

OPS-H81

cooling fan

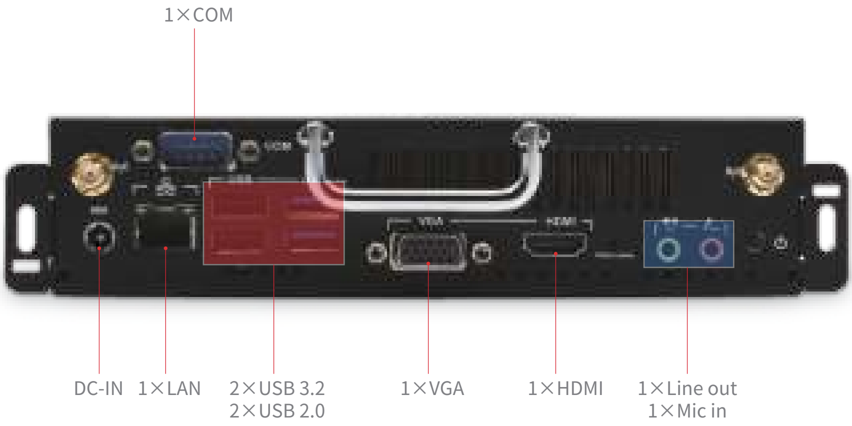
FEATURES

- Aluminum enclosure
- Intel H81 PCH, supporting Intel 4th LGA1150 processor
- Support dual channel DDR3-1600MHz up to 16GB
- mSATA, SATA3.0
- Standard OPS interface
- Intelligent cooling fan, low power consumption

APPLICATIONS

- Digital Signage
- POS Systems
- Power and Energy
- Logistics

I/O INTERFACES



SPECIFICATIONS

CPU	4th Gen Intel Haswell FCLGA115
Memory	2×DDR3-1600MHz, Max 16GB
Storage	1×mSATA SSD, 1×SATA 3.0
I/O Interface	1×LAN, 1×COM, 2×USB 3.2, 2×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×VGA
GPU	Intel HD Graphics
Size	195mm×181mm×42.5mm
Power	12~19V DC-in
Temperature	-15°C~50°C

OPS-H110

cooling fan

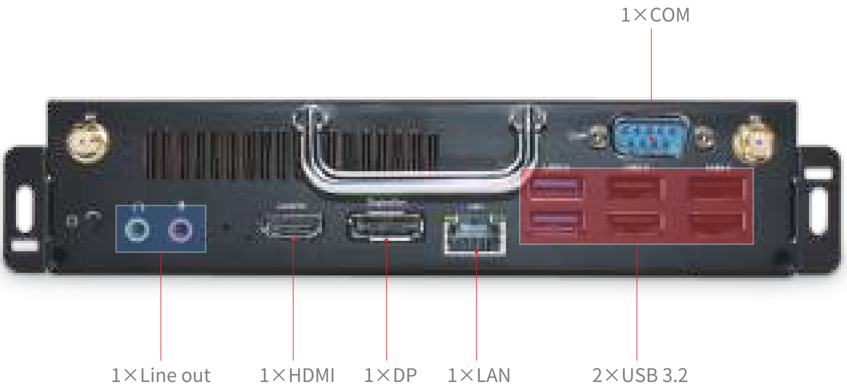
FEATURES

- Aluminum enclosure
- Intel H110 (or B150) PCH, supporting Skylake-S/Kabylake-S processor
- Support dual channel DDR4-2133MHz up to 32GB
- M.2 interface for SSD, wifi, 4G module
- Standard OPS interface
- Intelligent cooling fan, low power consumption

APPLICATIONS

- Manufacturing
- Rail Transportation
- New Energy

I/O INTERFACES



SPECIFICATIONS

CPU	6th Gen Intel Skylake-S LGA1151	th Gen Intel Kabylake-S LGA1151
Memory	2×SO-DIMM DDR4-2133MHz, Max 32GB	
Storage	1×2242 SSD or 4G, 1×SATA 3.0	
I/O Interface	1×LAN, 1×COM, 2×USB 3.2, 4×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×DP	
GPU	Intel HD Graphics	
Size	195mm×202mm×42.5mm	
Power	12~19V DC-in	
Temperature	-15°C~50°C	

MV-06

Fanless

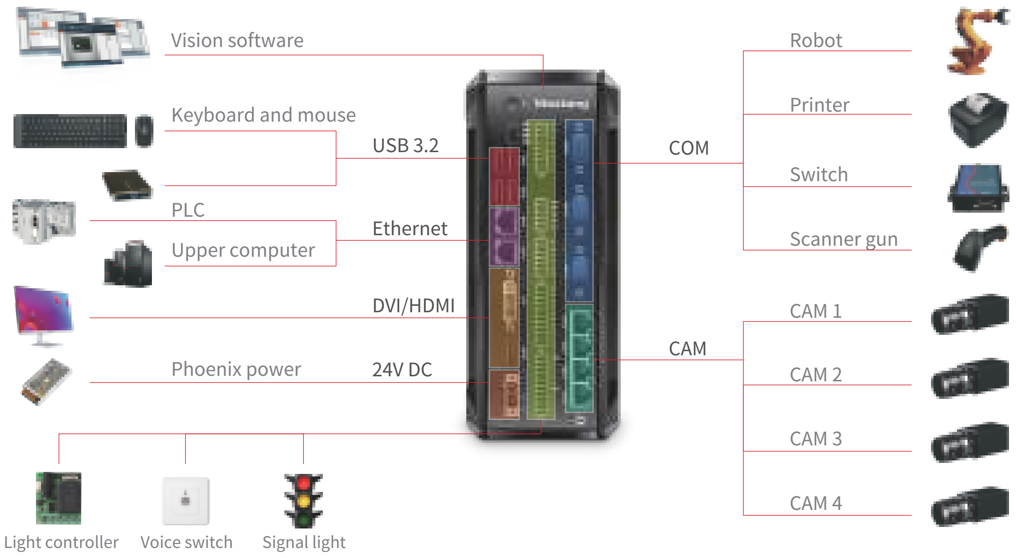
FEATURES

- CPU: Intel Celeron/Whiskey Lake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 2xLAN, 4xLAN PoE, 3xCOM, 4xUSB3.2,
- 8x GPIO(DO), 8x GPIO(DI),
- Display via: DVI, HDMI
- Storage: 1xM.2 for SSD or 4G, 1x M.2 for 2280 SSD

APPLICATIONS

- Manufacturing
- Rail Transportation
- New Energy

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 4205U	i3 8145U	i5 8265U	i7 8565U/8665U
Memory	2×SO-DIMM DDR4-2400/2133 MHz, Max 64GB			
Storage	1×M.2 for 2242/2280 SSD or 4G, 1×M.2 for 2280 SSD and NVME SSD			
I/O Interface	2×LAN, 4×LAN PoE, 3×COM, 4×USB 3.2, 1×USB 2.0, 16×GPIO, 1×HDMI, 1×DVI			
GPU	Integrated Graphics			
Size	90mm×210mm×150mm			
Power	24V DC-in			
Temperature	0°C~50°C			

MV-06C

Smart Fan/Fanless

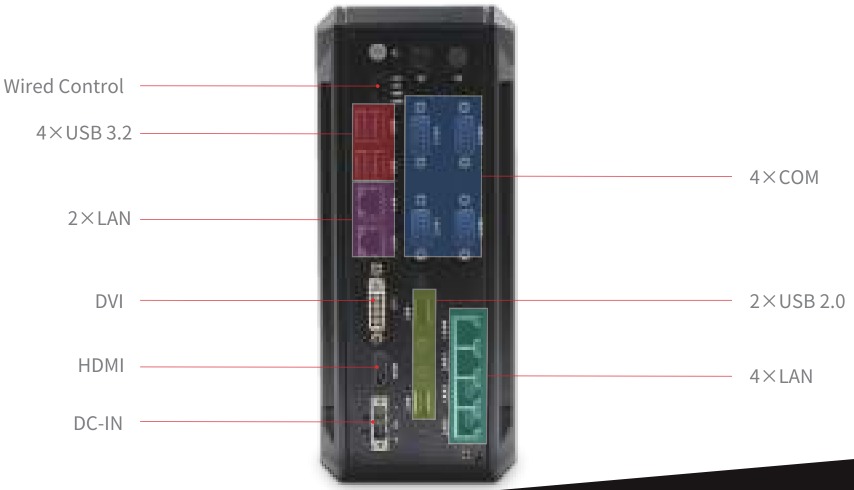
FEATURES

- CPU: Intel Whiskey Lake-U/Tiger Lake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 6xLAN, 4xCOM, 4xUSB3.2, 2x USB2.0
- Display via: DVI, HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: 1xM.2 for SSD or 4G, 1x M.2 for 2280 SSD

APPLICATIONS

- Manufacturing
- Rail Transportation
- New Energy

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron 4205U i3 8145U i5 8265U i7 8665U Celeron 6305 i5 1115G4 i5 1145G7E
Memory	2×SO-DIMM DDR4, Max 64GB
Storage	1×M.2_B 2242/2280 for SSD or 4G, 1×M.2_M for 2280 SSD
I/O Interface	6×LAN, 4×COM, 4×USB 3.2, 2×USB 2.0, 1×HDMI, 1×DVI
GPU	Integrated Graphics
Size	90mm×220mm×150mm
Power	24V DC-in
Temperature	-20°C~60°C

DT-8803H-E1

Fanless

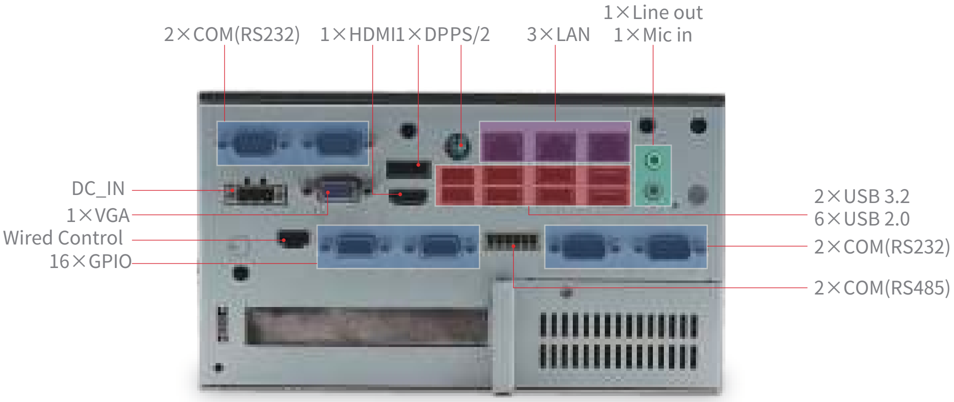
FEATURES

- CPU: Intel Haswell Processor with B85 Chipset
- Memory: 2x SO-DIMM DDR3L up to 16GB
- I/O Interface: 3xLAN, 6xCOM, 2x USB3.2, 6x USB2.0, 16xGPIO
- 2xUSB2.0 header, 1x USB3.2 Dongle Onboard.
- Display via: VGA, DP, HDMI
- Storage: 1x M.2 for 2280 SSD , SATA

APPLICATIONS

- Surveillance
- Traffic Monitoring
- Automation

I/O INTERFACES



SPECIFICATIONS

CPU	B85 Chipset +Haswell
Memory	2×SO-DIMM DDR3L, Max 16GB
Storage	1×M.2 for 2280 SSD, 1×M.2 4G/5G, 2×SATA 2.5, 1×M.2 for WiFi
I/O Interface	3×LAN, 6×COM, 1×SIM, 2×USB 3.2, 6×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI 1×DP, 1×VGA, 1×PS/2, 16×GPIO
GPU	Intel HD Graphics
Size	220mm×125mm×227.5mm
Power	16~36V DC-in
Temperature	0°C~50°C

UMIF SERIES

Fanless

FEATURES

- Supports Intel 8th Whiskey Lake and 11th Tiger Lake Core processors.
- Can be installed horizontally or on a DIN rail.
- Built-in 1M ferroelectric storage for storing core data.
- High-speed industrial isolation digital IO (4×DI, 4×DO).
- Supports system imaging functionality.
- Supports multiple PLC open development platforms (CODYSYS, LOGICLAB, KW).
- Supports TSN technology.
- Modular design, allowing for the expansion of multiple interfaces (CAN, RS232, RS485, LAN, 5G, Wi-Fi).

APPLICATIONS

- High real-time edge computing control for industrial robots, AGVs, AGCs, AMRs, and PLC industrial control.

I/O INTERFACES

SPECIFICATIONS

CPU	4205U	i3-8145	i5-8265U	i7-8665U	6305	i3-11154	i5-1145G7	i7-1185G7
Memory	2×SO-DIMM DDR4, Max 64GB							
Storage	1×SATA, 1×M.2 (SATA)							
I/O Interface	2×USB3.2, 2×USB2.0, 2×LAN,2×COM, 1×HDMI, 1×DVI, GPIO, Mini PCIe							
GPU	Integrated Intel Iris Xe/UHD Graphics							
Size	200mm×140mm×60mm							
Power	9~36V DC-in							
Temperature	-20°C~60°C							

ULTRA-COMPACT MINI PC

MTN-GL50

Smart Fan

FEATURES

- CPU: Intel Gemini Lake Processor
- Memory: LPDDR4 up to 8 GB
- I/O Interface: 2xLAN, 5x USB3.2, 1x Micro SD
- Display via: 2x HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: 1x M.2 for 2280 SSD, SATA
- Dimension: 116mm x 116mm x 40.7mm

APPLICATIONS

- Office
- Commercial
- Home

I/O INTERFACES

SPECIFICATIONS

CPU	J4125
Memory	LPDDR4 upto 2400 MT/s, Max 8GB
Storage	1×M.2 for WiFi+BT, 1×M.2 for WiFi and Bluetooth
I/O Interface	5×USB 3.0,1×Line out, 2×HDMI, 1×micro SD, 2×LAN
GPU	Intel UHD Graphics 600
Size	116mm×116mm×40.7mm
Power	12V
Temperature	0°C~50°C

MTN-FP50

Smart Fan

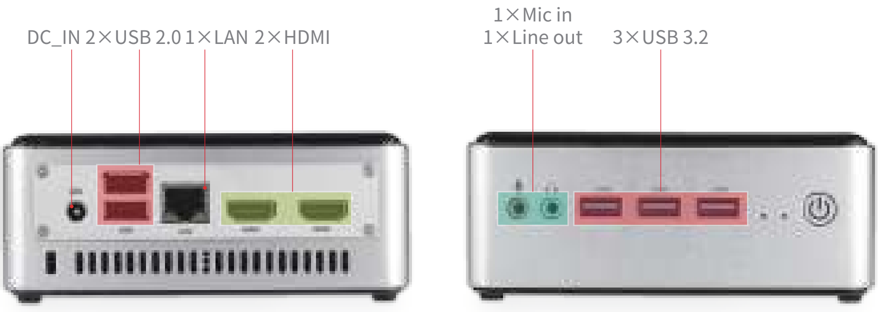
FEATURES

- CPU: AMD Ryzen Mobile Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 1xLAN, 3xUSB3.2, 2x USB2.0
- Display via: 2x HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: SATA3.0, 1x M.2 for 2280 SSD NVMe or SATA
- Dimension: 130mm x 128mm x 52mm

APPLICATIONS

- Office
- Gaming
- Entertainment

I/O INTERFACES



SPECIFICATIONS

CPU	3020E	2500U	3500U
Memory	2×DDR4, Max 64GB		
Storage	1×M.2 for 2280 SSD(NVMe only for 2500U/3500U), 1×SATA 3.0		
I/O Interface	1×LAN, 3×USB 3.2, 2×USB 2.0, 1×Mic in, 1×Line out, 2×HDMI		
GPU	Radeon™ Vega Graphics		
Size	130mm×128mm×52mm		
Power	12V DC_in		
Temperature	0°C~50°C		

MTN-BW50

Smart Fan

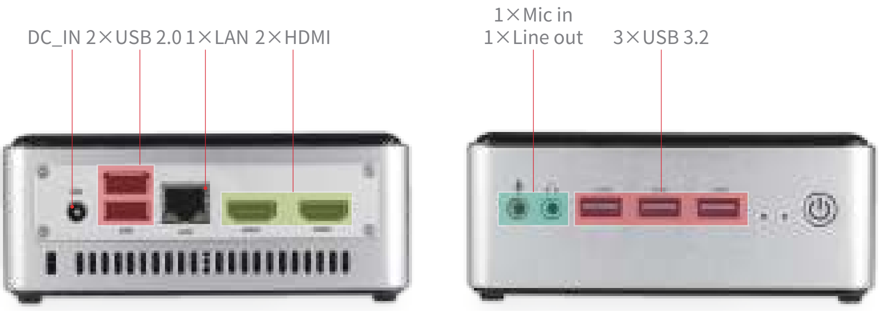
FEATURES

- CPU: Intel Broadwell/Haswell Processor
- Memory: 2x SO-DIMM DDR3L up to 16 GB
- I/O Interface: 1xLAN, 3x USB3.2, 2x USB2.0
- Display via: 2x HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: 1x M.2 for 2280 SSD, SATA3.0

APPLICATIONS

- Office
- Entertainment
- Live Streaming

I/O INTERFACES



SPECIFICATIONS

CPU	i3 5005U	i5 4200U	i7 5500U
Memory	2×DDR3L, Max 16GB		
Storage	1×M.2 for 2280 SSD, 1×SATA 3.0(2.5 inches)		
I/O Interface	1×LAN, 3×USB 3.2, 2×USB 2.0, 1×Mic in, 1×Line out, 2×HDMI		
GPU	Intel HD Graphics		
Size	130mm×128mm×52mm		
Power	12V DC_in		
Temperature	0°C~50°C		

MTN-TL50

Smart Fan

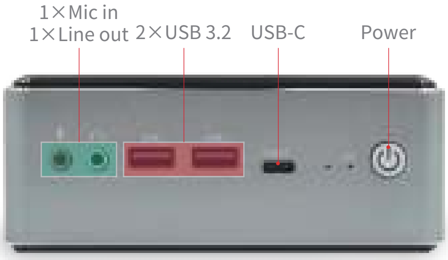
FEATURES

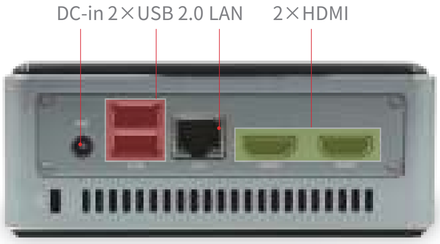
- CPU: Intel Tiger Lake Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 1xLAN, 2xUSB3.2, 2x USB2.0, 1xUSB-C
- Display via: 2x HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: SATA3.0, 1x M.2 for 2280 SSD NVMe
- Dimension: 130mm x 128mm x 52mm

APPLICATIONS

- Office
- Commercial
- Home
- Gaming

I/O INTERFACES





SPECIFICATIONS

CPU	Celeron 6305	i3-1115G4	i5-1135G7	i7-1165G7
Memory	Dual Channel SO-DIMM DDR4, Max 64GB			
Storage	1×M.2 for NVMe 2280 SSD, 1×SATA 3.0, 1×M.2 for WiFi and Bluetooth			
I/O Interface	2×USB 3.0, 2×USB 2.0, 1×Mic in, 1×Line out, 2×HDMI, 1×USB-C, 1×LAN			
GPU	Intel Integrated Graphics			
Size	130mm×128mm×52mm			
Power	12V/19V			
Temperature	0°C~50°C			

MTN-FP650

Smart Fan

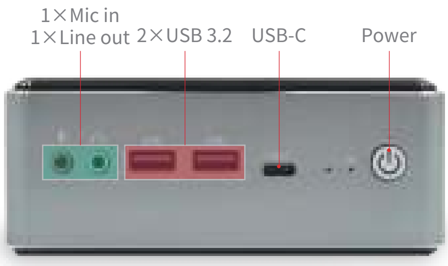
FEATURES

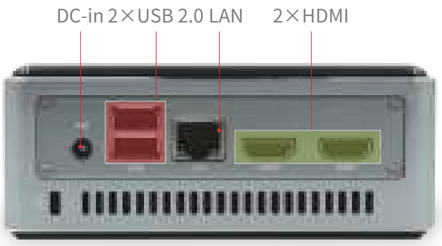
- CPU: AMD Ryzen 4000/5000 Series Mobile Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 1xLAN, 2xUSB3.2, 2x USB2.0, 1xUSB-C
- Display via: 2x HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: SATA3.0, M.2 for 2280 SSD
- Dimension: 130mm x 128mm x 52mm

APPLICATIONS

- Office
- Commercial
- Home

I/O INTERFACES





SPECIFICATIONS

CPU	4300U	4500U	4600U	4700U
Memory	Dual Channel SO-DIMM DDR4, Max 64GB			
Storage	1×M.2 for 2280 SSD, 1×SATA 3.0, 1×M.2 for WiFi and Bluetooth			
I/O Interface	2×USB 3.2, 2×USB 2.0, 1×Mic in, 1×Line out, 2×HDMI, 1×Type-C/USB 3.2 Gen 2, 1×LAN			
GPU	AMD Radeon™ Vega Graphics			
Size	130mm×128mm×52mm			
Power	12V/19V			
Temperature	0°C~50°C			

VFFP-30

Smart Fan

FEATURES

- CPU: Ryzen™ 5 2500U, 3500U and V1605B Processor
- Memory: 2x SO-DIMM DDR4 up to 32 GB
- I/O Interface: 2xLAN, 1xCOM, 2xUSB3.2, 4x USB2.0, USB-C
- Display via: DP, HDMI
- Storage: 1x M.2 2280 SSD, 1x M.2 2242 SSD or 3G/4G

APPLICATIONS

- Office
- Gaming
- Live Streaming

I/O INTERFACES

SPECIFICATIONS

CPU	3300U	2500U	3500U
Memory	2×DDR4, Max 32GB		
Storage	1×M.2 2280 NVMe SSD, 1×M.2 2242 SSD or 4G		
I/O Interface	2×LAN, 2×USB 3.0, 4×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×DP, 1×Type-c		
GPU	Radeon™ Vega Graphics		
Size	191mm×151mm×29mm		
Power	12/19V DC_in		
Temperature	0°C~50°C		

VFWL-30

Smart Fan

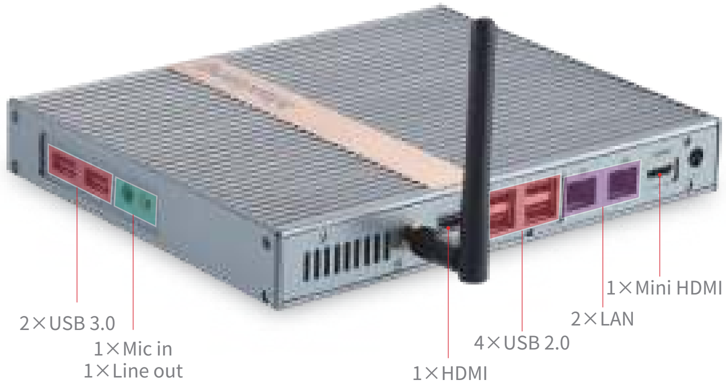
FEATURES

- CPU: Intel Whiskey Lake U Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 2xLAN, 1xCOM(Optional), 2xUSB3.2, 4x USB2.0
- Display via: DP, HDMI & mini HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: 1x M.2 2280 SSD(NVMe), 1x M.2 2242 SSD or 3G/4G

APPLICATIONS

- Office
- Entertainment
- Live Streaming

I/O INTERFACES



SPECIFICATIONS

CPU	i3 8145U	i5 8265U
Memory	2×SO-DIMM DDR4-2400/2133MHz, Max 64GB	
Storage	1×M.2 for 2280 NVMe SSD, 1×M.2 2240 or 4G	
I/O Interface	2×LAN, 2×USB 3.0, 4×USB 2.0, 1×Mic in, 1×Line out, 1×HDMI, 1×Mini HDMI	
GPU	Intel HD Graphics	
Size	191mm×151mm×29mm	
Power	19V DC_in	
Temperature	-20°C~60°C	

FXTL-10

Smart Fan

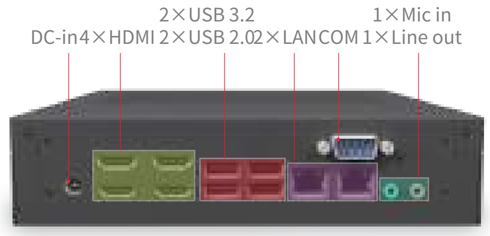
FEATURES

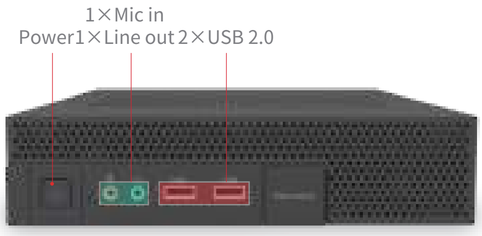
- CPU: Intel Tiger Lake-U Processor
- Memory: 2x SO-DIMM DDR4 up to 64 GB
- I/O Interface: 2xLAN, 1xCOM , 2x USB3.2, 4x USB2.0
- Display via: 4x HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: 1x M.2 for SSD NVMe, SATA3.0
- Expansion: 1x M.2 for WiFi, 1x M.2 for 4G/5G, 1x PCIe2x

APPLICATIONS

- Office
- Commercial
- Home
- Gaming

I/O INTERFACES





SPECIFICATIONS

CPU	Celeron 6305	i3-1115G4	i5-1145G7	i7-1165G7
Memory	Dual Channel SO-DIMM DDR4, Max 64GB			
Storage	1× M.2 for SSD NVMe, 1×SATA 3.0, 1×M.2 for WiFi, 1×M.2 for 4G/5G			
I/O Interface	2×USB 3.2, 4×USB 2.0, 2×Mic in, 2×Line out, 4×HDMI, 1×COM, 2×LAN			
GPU	Intel Iris Xe/UHD Graphics			
Size	208mm×190mm×45mm			
Power	12V			
Temperature	-20°C~60°C			

FX-J4125

Smart Fan

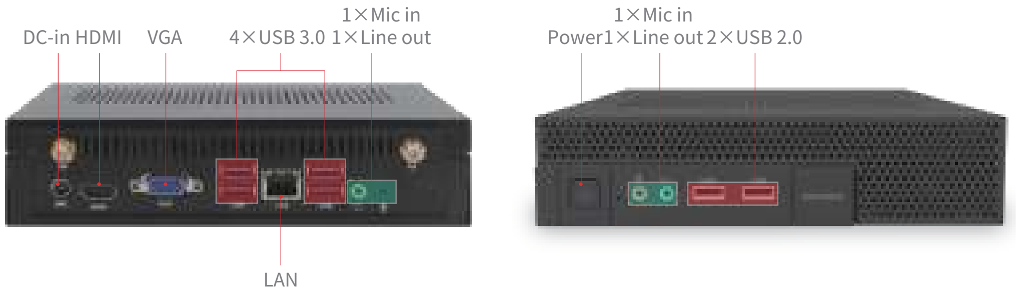
FEATURES

- CPU: Intel Celeron Processor J4125
- Memory: 2x SO-DIMM DDR4 up to 8GB
- I/O Interface: 1xLAN, 4xUSB3.2, 2x USB2.0
- Display via: VGA, HDMI
- Ethernet: 10/100/1000 Mbps
- Storage: 2xSATA, M.2 for SSD NVMe
  Expansion: WiFi onboard

APPLICATIONS

- Office
- Commercial
- Home

I/O INTERFACES



SPECIFICATIONS

CPU	J4125
Memory	DDR4×2, Max 32GB
Storage	1×M.2 SATA SSD
I/O Interface	4×USB 3.0, 2×USB 2.0, 2×Line out, 2×Mic in, 1×HDMI, 1×VGA, 1×LAN
GPU	Intel UHD 600
Size	205mm×190mm×45mm
Power	12V/19V
Temperature	-20°C~60°C

MTN+T24

Smart Fan

FEATURES

- 16.7M colors, multiple Display via VGA+HDMI
- 1920*1080 FHD Resolution 250cd/m2 Brightness
- 178 degree viewing angle, 5000:1 Contrast Ratio
- Support 75mm*75mm VESA mounting
- Elegant Design, Great for Space Saving
- One step to set up for use.

APPLICATIONS

- Office
- Commercial
- Home

SPECIFICATIONS

CPU	1305G	2500U	3500U
Memory	Radeon™ Vega Graphics		
Storage	2×SO-DIMM DDR4, Max 32GB		
I/O Interface	1×M.2 for NVMe 2280 SSD, 1×SATA		
GPU	3×USB 3.0, 2×USB 2.0, 1×Mic in, 1×Line out, 3×HDMI, 1×VGA, 1×LAN		
Size	23.8inch, 1920×1080 FULL HD		
Power	Win10 64bit, Linux 64bit		
Temperature	130mm×128mm×52mm (PC) , 598mm×132mm×485mm (display)		

DX6412

Fanless

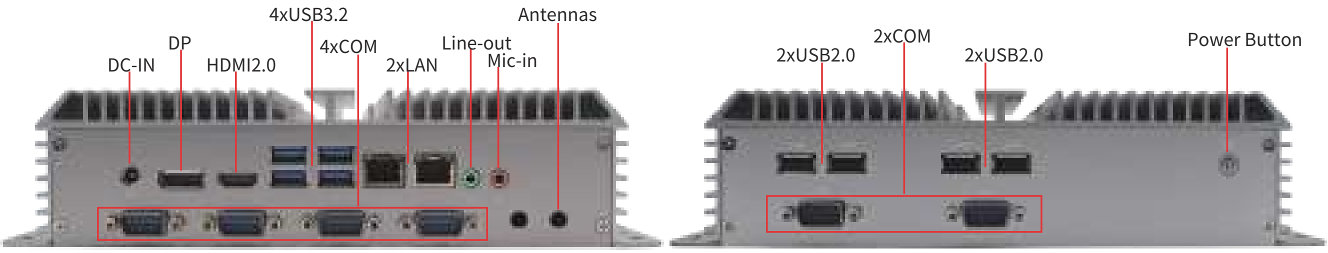
FEATURES

- CPU: Intel Elkhart Lake Celeron J6412 Processor
- Memory: Single Channel SO-DIMM DDR4 up to 32GB
- Display via: Intel UHD Graphics via DP, HDMI
- I/O Ports: 4xUSB3.2, 4xUSB2.0. 2xLAN, 6xCOM
- Ethernet: 10/100/1000Mbps
- Storage: SATA3.0, M.2 for SSD

APPLICATIONS

- Industrial Automation
- Manufacturing
- Network Security
- Surveillance

I/O INTERFACES



SPECIFICATIONS

CPU	J6412 (4 Cores/ 4 Threads)
Memory	Single Channel SO-DIMM DDR4, Max 32GB
Storage	SATA3.0,1x M.2 for 2280/2242 SATA SSD, optional 4G module
I/O Interface	4xUSB3.2, 4xUSB2.0. 2xLAN, 6xCOM, 1x DP, 1x HDMI
GPU	Intel UHD Graphics for 10th Gen Intel Processors
Size	255mm x 200mm x 60mm
Power	12V DC_in
Temperature	-20°C ~60°C

DXBYT-60

Fanless

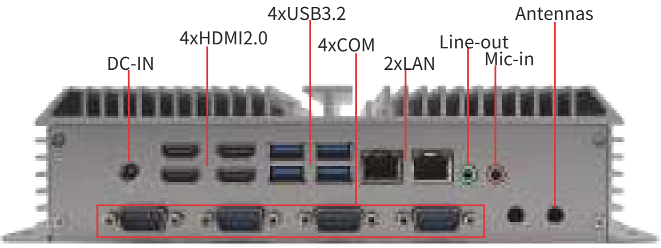
FEATURES

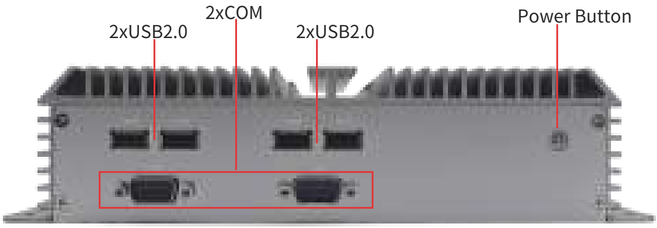
- CPU: Intel Bay Trail Processor
- Memory: Single Channel SO-DIMM DDR3L up to 8GB
- Display via: Intel HD Graphics via VGA, HDMI
- I/O Ports: 1xUSB3.2, 5xUSB2.0. 2xLAN, 6xCOM
- Ethernet: 10/100/1000Mbps
- Storage: SATA2.0, mSATA
- Dimension: 255mm x 220mm x 60mm

APPLICATIONS

- Industrial Automation
- Manufacturing
- Network Security
- Surveillance
- Smart Transportation

I/O INTERFACES





SPECIFICATIONS

CPU	J1800(2-core)	J1900(4-core)	N2940(4-core)
Memory	Single Channel SO-DIMM DDR3L, Max 8GB		
Storage	SATA2.0,mSATA		
I/O Interface	1xUSB3.2, 5xUSB2.0. 2xLAN, 6xCOM, VGA, HDMI		
GPU	Intel HD Graphics		
Size	255mm x 200mm x 60mm		
Power	12V DC-in		
Temperature	-20°C to 60°C		

DXAL-10

Fanless

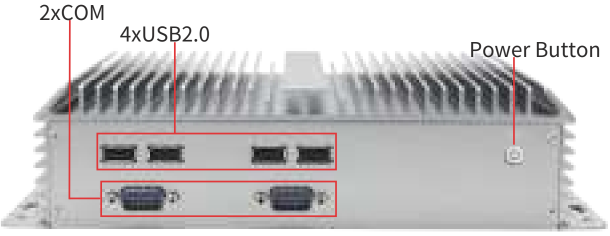
FEATURES

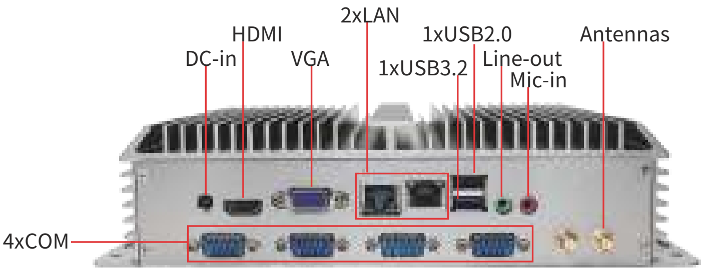
- CPU: Intel Alder Lake-U Series Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 64GB
- Display via: Intel Integrated Graphics via 4xHDMI2.0
- I/O Ports: 4xUSB3.2, 4xUSB2.0. 2xLAN, 6xCOM
- Ethernet: 10/100/1000/2500Mbps
- Storage: SATA3.0, M.2 for NVMe SSD

APPLICATIONS

- Industrial Automation
- Manufacturing
- Network Security
- Surveillance
- Digital Signage

I/O INTERFACES





SPECIFICATIONS

CPU	i7-1255U	i5-1235U	i3-1215U
Memory	Dual Channel SO-DIMM DDR4, Max 64GB		
Storage	1×M.2 for NVMe 2280 SSD,SATA		
I/O Interface	4xUSB3.2, 4xUSB2.0, 2xLAN, 6xCOM, 4x HDMI2.0		
GPU	Intel Iris Xe Graphics eligible/UHD Graphics depends on CPU		
Size	255mm x 200mm x 60mm		
Power	19V DC-in		
Temperature	-20°C ~60°C		

IXEHL-35

Fanless

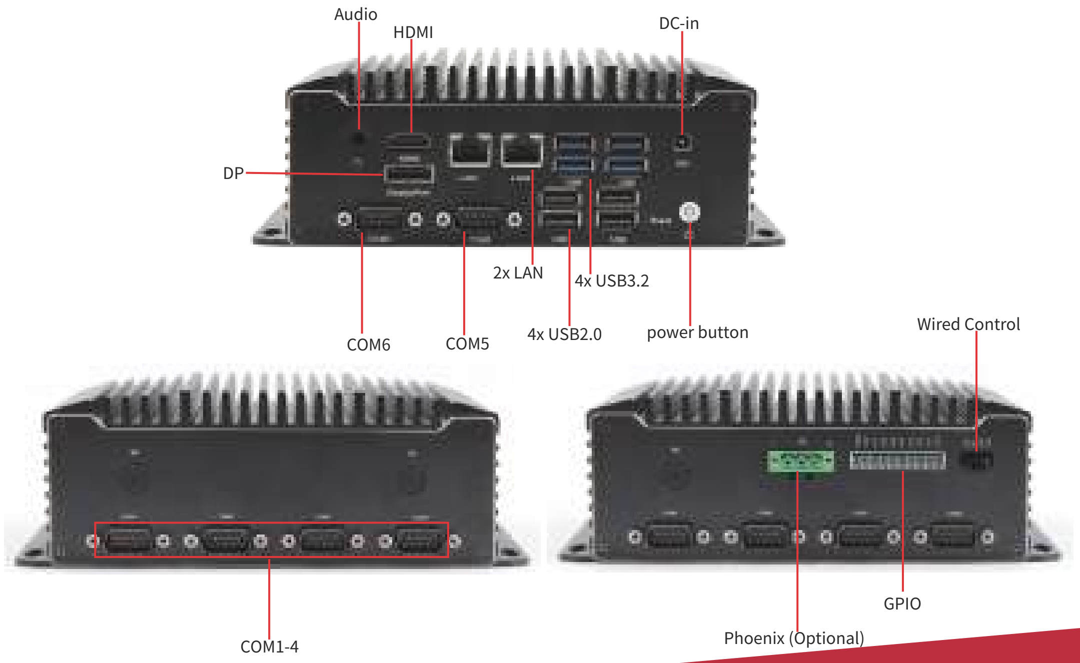
FEATURES

- CPU: Intel Celeron Processor J6412
- Memory: Single Channel SO-DIMM DDR4 up to 32 GB
- Display: Intel UHD Graphics, display via HDMI+DP
- Ethernet: 10/100/1000Mbps
- Storage: SATA3.0, mSATA

APPLICATIONS

- Industrial Automation
- Manufacturing
- Surveillance
- Digital Signage
- Network Appliances

I/O INTERFACES



SPECIFICATIONS

CPU	Celeron J6412
Memory	Single Channel SO-DIMM DDR4, Max 32GB
Storage	1x mSATA for SSD/4G Module, 1x SATA 2.5-inch HDD
I/O Interface	2xLAN, 6xCOM, 4xUSB3.2, 4xUSB2.0,DP, HDMI
GPU	Intel UHD Graphics based on CPU
Size	165mm x 125mm x 65mm
Power	12V DC IN
Temperature	-20°C to 60°C

MTN-AL50

Smart Fan

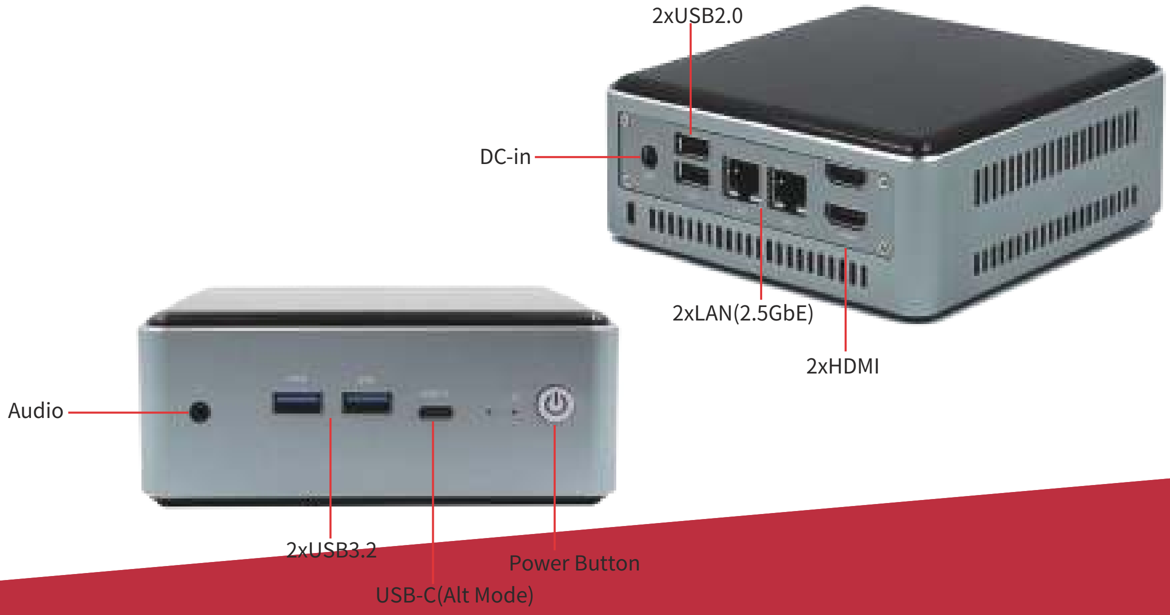
FEATURES

- CPU: 12th Gen Intel Alder Lake-P Series Processor
- Memory: Dual Channel DDR5 for Memory up to 64GB
- Display: Intel Integrated Graphics, Dual Displays via HDMI2.0
- I/O Ports: 2xUSB3.2, 2xUSB2.0, 2xLAN(2.5GbE), 2xHDMI2.0, USB-C, Audio
- Expansion: M.2 for WiFi and Bluetooth
- Storage: SATA3.0, M.2_2280 SSD NVMe

APPLICATIONS

- Collaboration
- Content Creation
- Workstations
- Home Entertainment

I/O INTERFACES



SPECIFICATIONS

CPU	i7-1260P	i5-1240P
Memory	Dual Channel SO-DIMM DDR5, Max 64GB	
Storage	1xM.2 for NVMe 2280 SSD, PCIe4.0 4X Signal, SATA3.0	
I/O Interface	2xUSB3.2, 2xUSB2.0, 2xLAN(2.5GbE), 2xHDMI2.0, USB-C, Audio	
GPU	Intel Integrated Graphics (Iris Xe/UHD Graphics depends on CPU)	
Size	128 mm x 130 mm x 51.5mm	
Power	19V/20V DC-in	
Temperature	0°C to 50°C	

MTN-FP650

Smart Fan

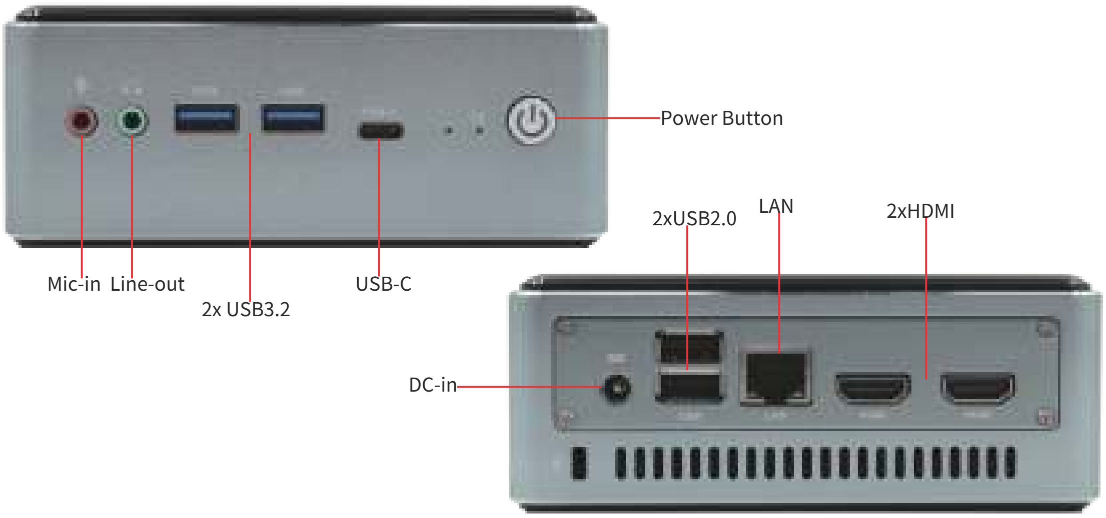
FEATURES

- CPU: AMD Ryzen™ Mobile Processors 4000 Series("Zen 2")
- Memory: Dual Channel DDR4 for Memory up to 64GB
- Display: AMD Radeon™ Graphics, Dual Displays via HDMI2.0
- I/O Ports: 2xUSB3.2, 2xUSB2.0, 1xLAN, 2xHDMI, USB-C Gen2
- Expansion: M.2 for WiFi and Bluetooth
- Storage: SATA3.0, M.2 for 2280 SSD
- Power: 12V/19V DC-in

APPLICATIONS

- Collaboration
- Content Creation
- Workstations
- Home Entertainment

I/O INTERFACES



SPECIFICATIONS

CPU	Ryzen3 4300U	Ryzen5 4500U	Ryzen7 4700U
Memory	Dual Channel SO-DIMM DDR4, Max 64GB		
Storage	1xM.2 f or 2280 SSD, Supports NVMe or SATA,SATA3.0		
I/O Interface	2xUSB3.2, 2xUSB2.0, 1xLAN, 2xHDMI, USB-C Gen2, Line-out, Mic-in,		
GPU	AMD Radeon™ Vega Graphics		
Size	128 mm x 130 mm x 52mm		
Power	12V/19V DC-in		
Temperature	-20°C to 70°C		

MTN-FP650

Smart Fan

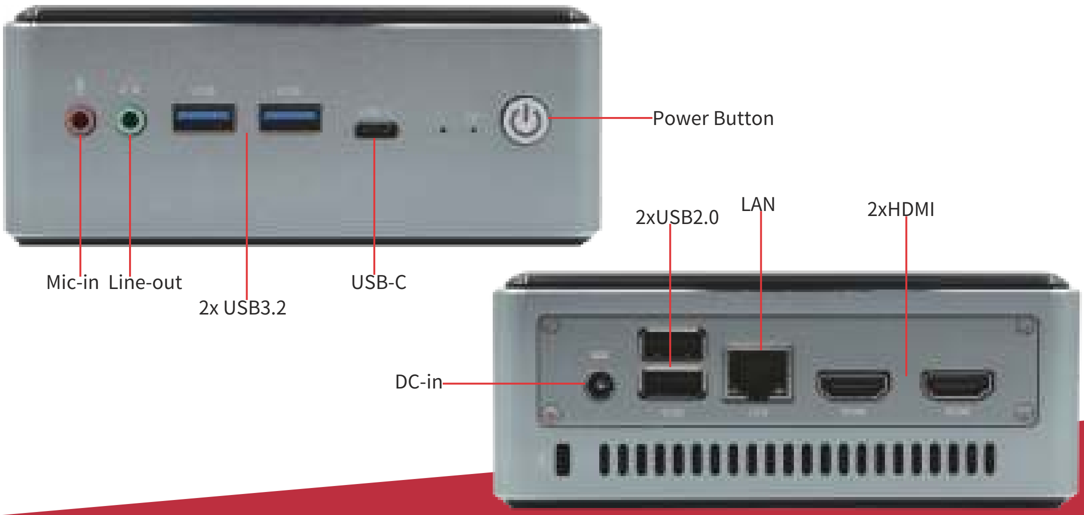
FEATURES

- CPU: AMD Ryzen™ Mobile Processors 5000 Series
- Memory: Dual Channel DDR4 for Memory up to 64GB
- Display: AMD Radeon™ Graphics, Dual Displays via HDMI2.0
- I/O Ports: 2xUSB3.2, 2xUSB2.0, 1xLAN, 2xHDMI, USB-C Gen2
- Expansion: M.2 for WiFi and Bluetooth
- Storage: SATA3.0, M.2 for 2280 SSD

APPLICATIONS

- Collaboration
- Content Creation
- Workstations
- Home Entertainment

I/O INTERFACES



SPECIFICATIONS

CPU	Ryzen3 5300U/5400U	Ryzen5 5500U/5600U	Ryzen7 5700U/5800U
Memory	Dual Channel SO-DIMM DDR4, Max 64GB		
Storage	1xM.2 for 2280 SSD, Supports NVMe or SATA, SATA3.0		
I/O Interface	2xUSB3.2, 2xUSB2.0, 1xLAN, 2xHDMI, USB-C Gen2, Line-out, Mic-in		
GPU	AMD Radeon™ Graphics		
Size	128 mm x 130 mm x 52mm		
Power	12V/19V		
Temperature	-20°C~70°C		

MTN-FP650

Smart Fan

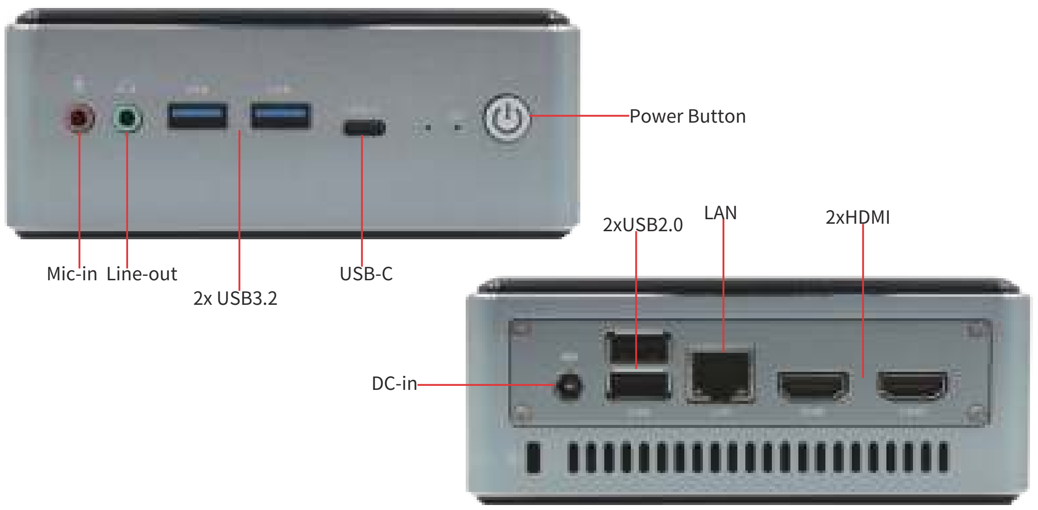
FEATURES

- CPU: AMD Ryzen™ 5600H Mobile Processor
- Memory: Dual Channel DDR4 for Memory up to 64GB
- Display: AMD Radeon™ Graphics, Dual Displays via HDMI2.0
- I/O Ports: 2xUSB3.2, 2xUSB2.0, 1xLAN, 2xHDMI, USB-C Gen2
- Expansion: M.2 for WiFi and Bluetooth
- Storage: SATA3.0, M.2 for 2280 SSD

APPLICATIONS

- Collaboration
- Content Creation
- Workstations
- Home Entertainment

I/O INTERFACES



SPECIFICATIONS

CPU	Ryzen 5 5600H
Memory	Dual Channel SO-DIMM DDR4, Max 64GB
Storage	1xM.2 for 2280 SSD, Supports NVMe or SATA, SATA3.0
I/O Interface	2xUSB3.2, 2xUSB2.0, 1xLAN, 2xHDMI, USB-C Gen2, Line-out, Mic-in
GPU	AMD Radeon™ Graphics
Size	128 mm x 130 mm x 52mm
Power	19V DC-in
Temperature	0°C to 50°C

MTN-FP750

Smart Fan

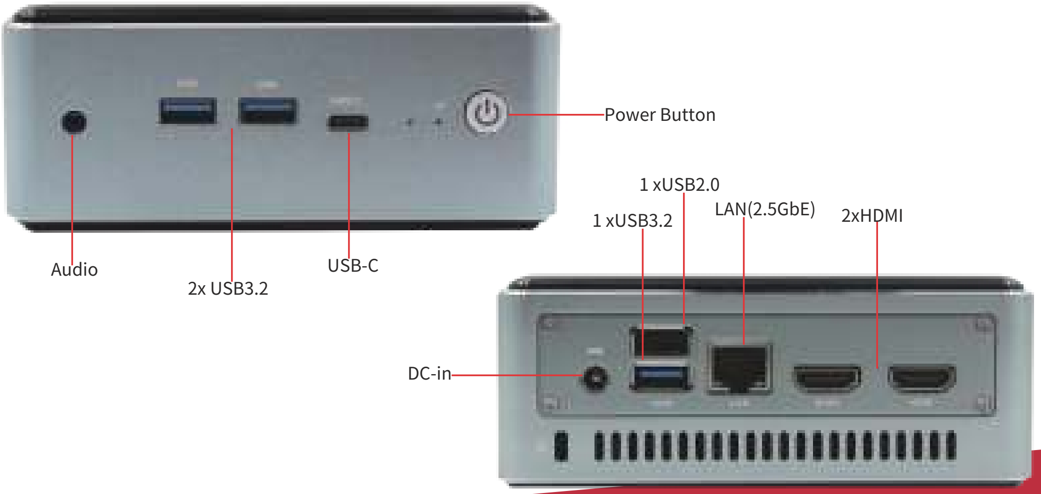
FEATURES

- CPU: AMD Ryzen™ 6000 Series Mobile Processors
- Memory: Dual Channel DDR5 for Memory up to 64GB
- Display: AMD Radeon™ Graphics, Dual Displays via HDMI2.0
- I/O Ports: 3xUSB3.2, 1xUSB2.0, 1xLAN(2.5GbE), 2xHDMI, USB-C, Audio
- Expansion: M.2 for WiFi and Bluetooth
- Storage: SATA(FPC), M.2 for 2280 SSD

APPLICATIONS

- Collaboration
- Content Creation
- Workstations
- Home Entertainment
- Gaming

I/O INTERFACES



SPECIFICATIONS

CPU	Ryzen™ 7 6800H	Ryzen™ 5 6600H
Memory	Dual Channel DDR5 for Memory up to 64GB	
Storage	1xM.2 for 2280 NVMe SSD,1x FPC SATA interface	
I/O Interface	3xUSB3.2, 1xUSB2.0, 1xLAN(2.5GbE), 2xHDMI, USB-C, Audio	
GPU	AMD Radeon™ Graphics	
Size	128 mm x 130 mm x 52mm	
Power	19V/20V DC-in	
Temperature	0°C to 50°C	

MUC-5095

Smart Fan

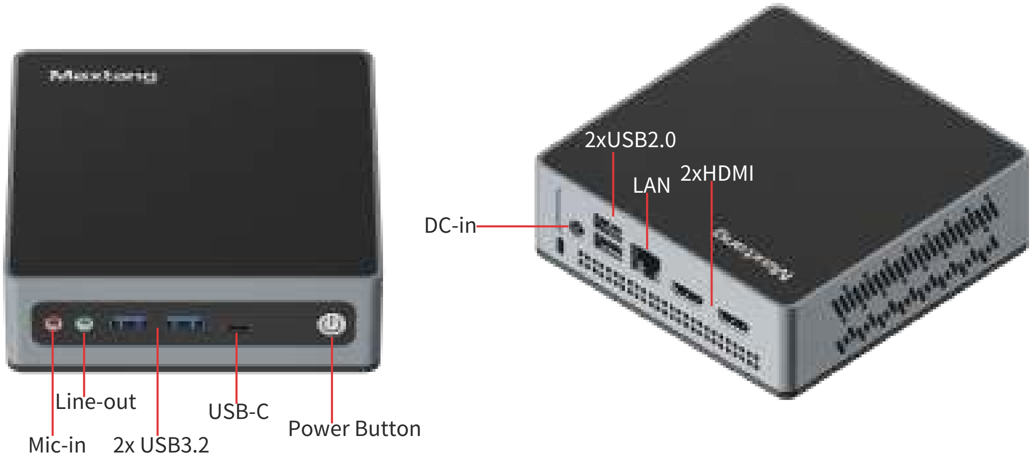
FEATURES

- CPU: Intel Celeron Processor N5095/N5095A
- Memory: Dual Channel DDR4 for Memory up to 32GB
- Display: Intel Integrated Graphics, Dual Displays via HDMI2.0
- Expansion: M.2 for WiFi and Buletooth
- Storage: M.2 for 2280 NVMe/SATA SSD

APPLICATIONS

- Kiosks
- Office
- Home Entertainment
- Everyday use

I/O INTERFACES



SPECIFICATIONS

CPU	N5095/N5095A
Memory	Dual Channel SO-DIMM DDR4, Max 32GB
Storage	1xM.2 for 2280 NVMe/SATA SSD,1xM.2 for WiFi and Bluetooth
I/O Interface	2xUSB3.2, 2xUSB2.0, 1xLAN, 2xHDMI, USB-C, Line-out, Mic-in
GPU	Integrated Intel UHD Graphics
Size	128.7mm x 128.7mm x 41.5mm
Power	12V DC IN
Temperature	0°C to 50°C

NX6412

Fanless

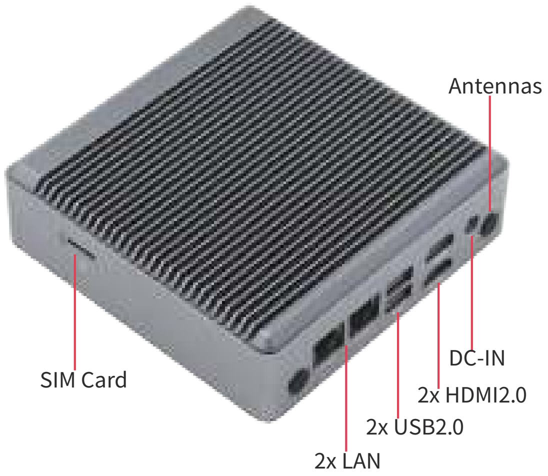
FEATURES

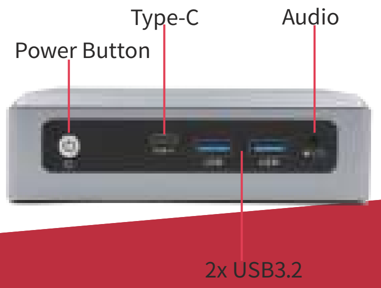
- CPU: Intel Elkhart Lake J6412 Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 32GB
- Display via: Intel Integrated Graphics display via 2xHDMI2.0
- I/O Ports: 2xLAN, 2xUSB3.2, 2xUSB2.0, Type-C, SIM
- Ethernet: 10/100/1000Mbps
- Storage: 1x M.2 2242/2280 SSD, SATA optional

APPLICATIONS

- Network Security
- Surveillance
- Digital Signage/Kiosks
- Office Collaboration

I/O INTERFACES





SPECIFICATIONS

CPU	J6412
Memory	Dual Channel SO-DIMM DDR4, Max 32GB
Storage	1xM.2 for 2242/2280 SSD (SATA ONLY) or 4G, SATA Optional
I/O Interface	2xLAN, 2xUSB3.2, 2xUSB2.0, Type-C, SIM, 2xHDMI2.0
GPU	Intel UHD Graphics for 10th Gen Intel Processors
Size	127mm x 127mm x 37mm
Power	12V DC-in
Temperature	- 20°C to 60°C

DSAL-35

Fanless

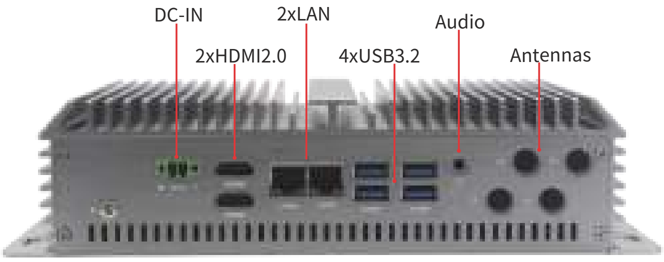
FEATURES

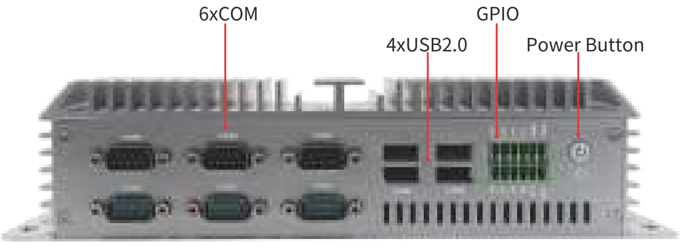
- CPU: Intel Alder Lake-U Series Processor
- Memory: Dual Channel SO-DIMM DDR5 up to 64GB
- Display via: Intel Integrated Graphics via 2xHDMI2.0
- I/O Ports: 4xUSB3.2, 4xUSB2.0. 2xLAN, 6xCOM
- Ethernet: Intel i219(1.0GbE)+Intel i226(2.5GbE)
- Storage: SATA3.0, M.2 for SATA/4G, M.2 for NVMe
- Dimension: 255mm x 165mm x 60mm

APPLICATIONS

- Industrial Automation
- Manufacturing
- Network Security
- Surveillance
- Smart Transportation

I/O INTERFACES





SPECIFICATIONS

CPU	i5-1235U
Memory	Dual Channel SO-DIMM DDR5, Max 64GB
Storage	1×M.2 for NVMe 2280 SSD,1×M.2 for SATA/4G
I/O Interface	4xUSB3.2, 4xUSB2.0. 2xLAN, 6xCOM, 2x HDMI2.0, 8xGPIO
GPU	Integrated Intel Iris Xe Graphics eligible
Size	255mm x 165mm x 60mm
Power	12V-35V DC-in
Temperature	-20°C ~60°C

VHEHL-30

Fanless

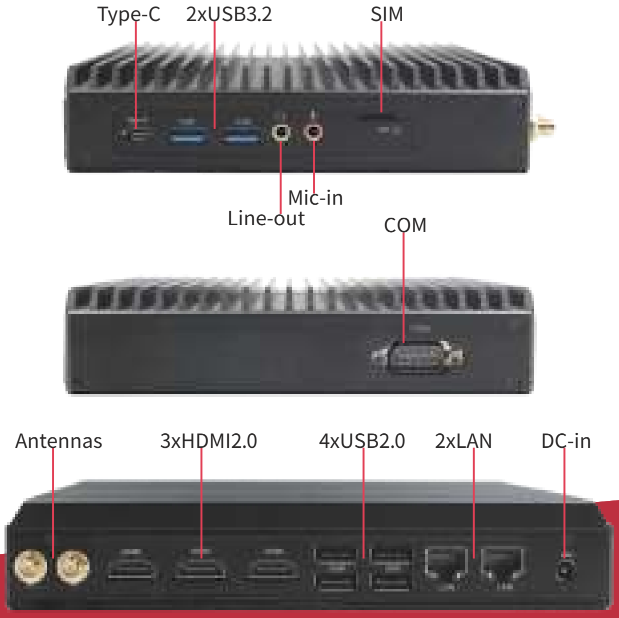
FEATURES

- CPU: Intel Elkhart Lake J6412 Processor
- Memory: Dual Channel SO-DIMM DDR4 up to 32GB
- Display via: Intel Integrated Graphics display via 3xHDMI2.0
- I/O Ports: 2xLAN, 1xCOM, 2xUSB3.2, 4xUSB2.0, Type-C, SIM
- Ethernet: 10/100/1000Mbps
- Storage: 2xM.2 for SSD

APPLICATIONS

- Kiosks/Digital Signage
- Workstations
- Network Security
- Surveillance

I/O INTERFACES



SPECIFICATIONS

CPU	J6412
Memory	Dual Channel SO-DIMM DDR4, Max 32GB
Storage	1xM.2 for 2280 NVMe SSD (PCIe 2X signal),1xM.2 for 2242/2280 SATA SSD or 4G
I/O Interface	2xLAN, 1xCOM, 2xUSB3.2, 4xUSB2.0, Type-C, SIM, 3xHDMI2.0
GPU	Intel UHD Graphics for 10th Gen Intel Processors
Size	191 mm x 151mm x 34 mm
Power	12V DC-in /12V~30V optional
Temperature	- 20°C to 60°C